(12) **United States Patent**
Ito et al.

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(45) **Date of Patent: Mar. 28, 2023**

(54) **SEMICONDUCTOR SUBSTRATE, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, AND METHOD OF MANUFACTURING SEMICONDUCTOR SUBSTRATE**

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(73) Assignee: **Kioxia Corporation**, Tokyo (JP)

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(30) **Foreign Application Priority Data**

Sep. 15, 2020 (JP) JP2020-154443

(51) **Int. Cl.**
H01L 29/06 (2006.01)
H01L 21/02 (2006.01)
H01L 27/06 (2006.01)
H01L 21/768 (2006.01)

(52) **U.S. Cl.**
CPC ***H01L 29/06*** (2013.01); ***H01L 21/02019*** (2013.01); ***H01L 21/76802*** (2013.01); ***H01L 27/0688*** (2013.01)

(58) **Field of Classification Search**
None
See application file for complete search history.

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(74) *Attorney, Agent, or Firm* — Oblon, McClelland, Maier & Neustadt, L.L.P.

(57) **ABSTRACT**

A semiconductor substrate includes a surface having a groove. The groove includes an inner bottom surface and an inner wall surface. The inner wall surface has a depression. The depression has a depth from a direction along a surface of the inner wall surface to a width direction of the groove. The substrate being exposed to the inner wall surface.

7 Claims, 22 Drawing Sheets

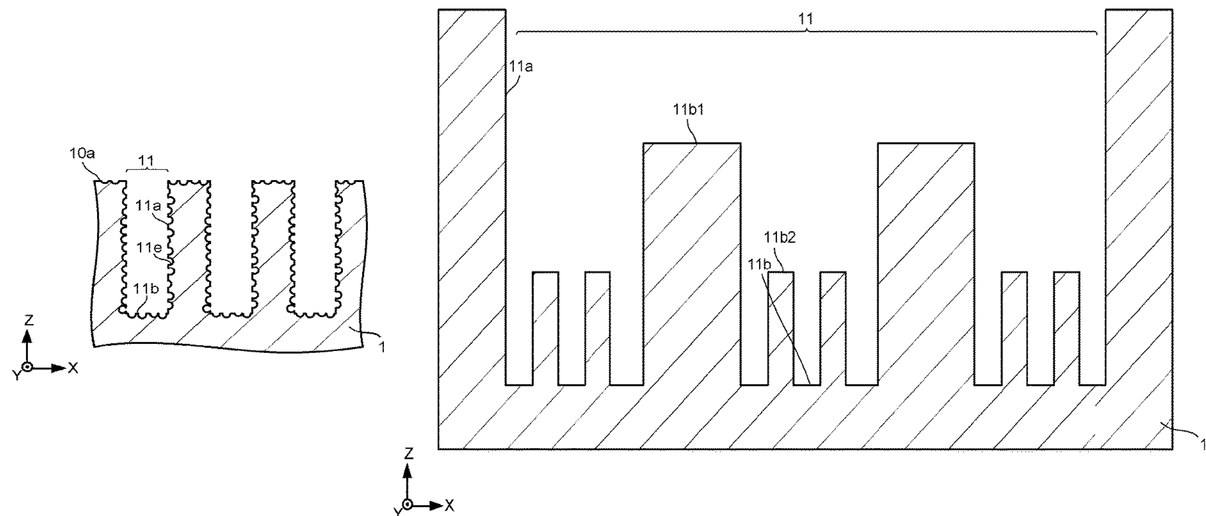

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FIG. 1

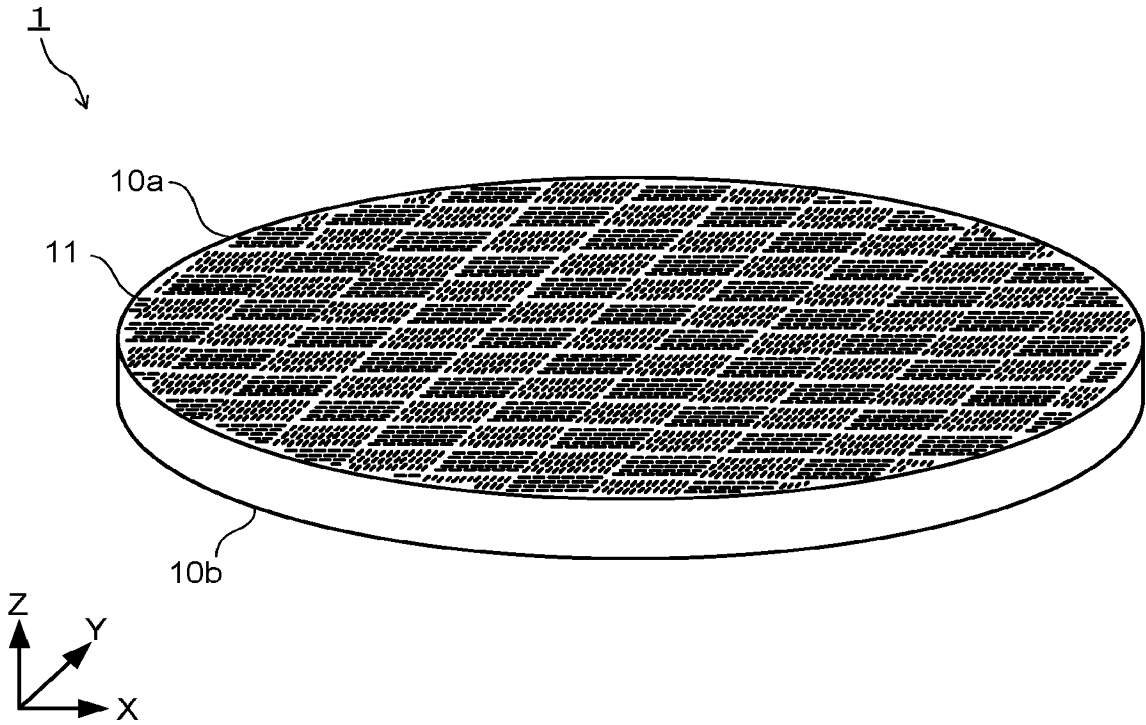


FIG. 2

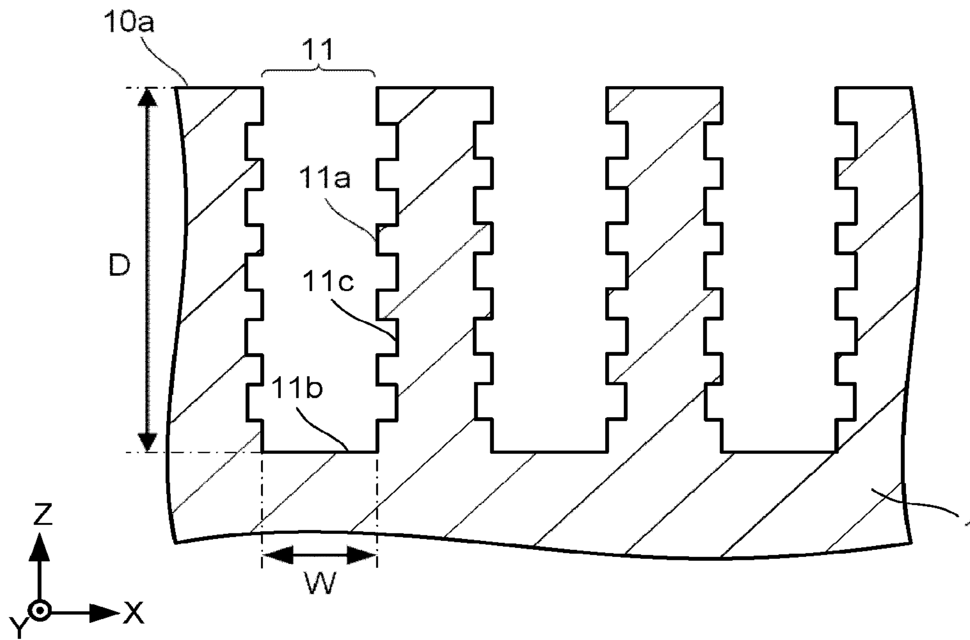


FIG. 3

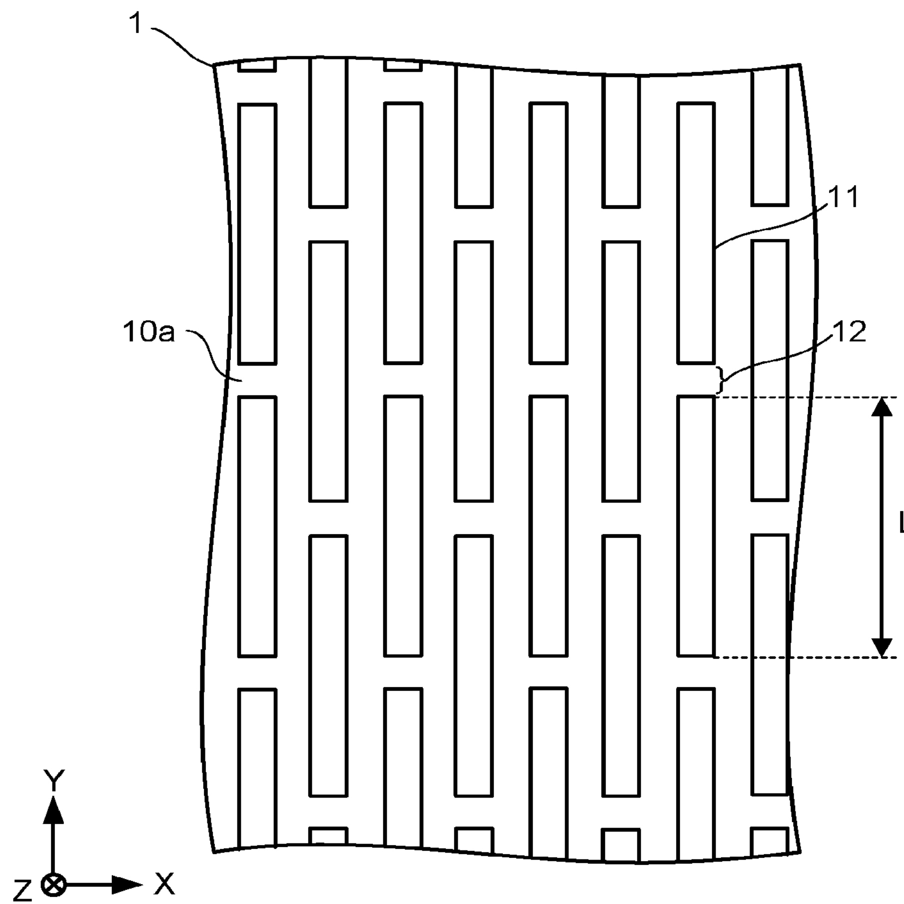


FIG. 4

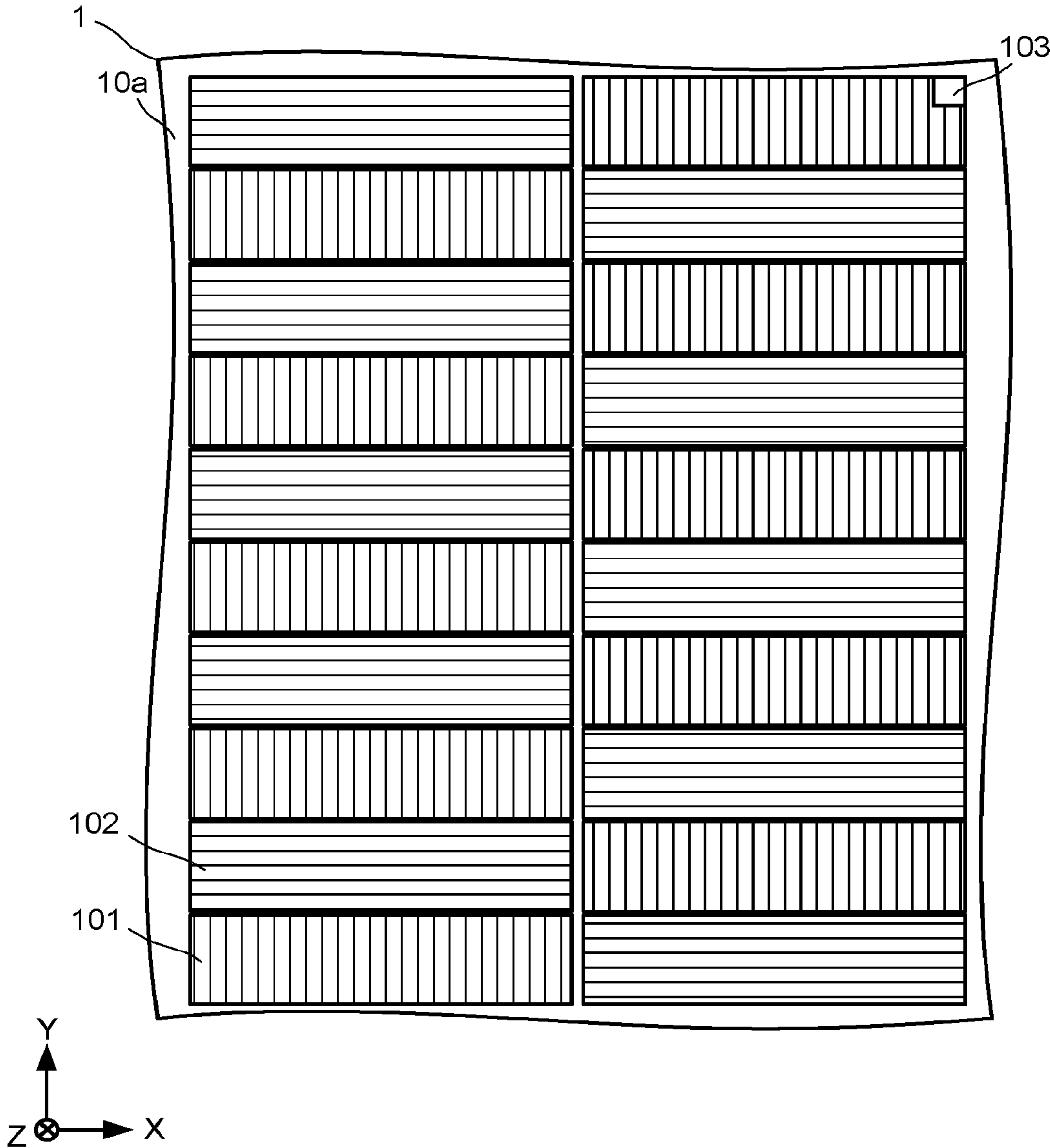


FIG. 5

102
112
11
111
101

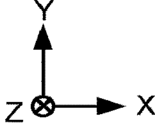


FIG. 6

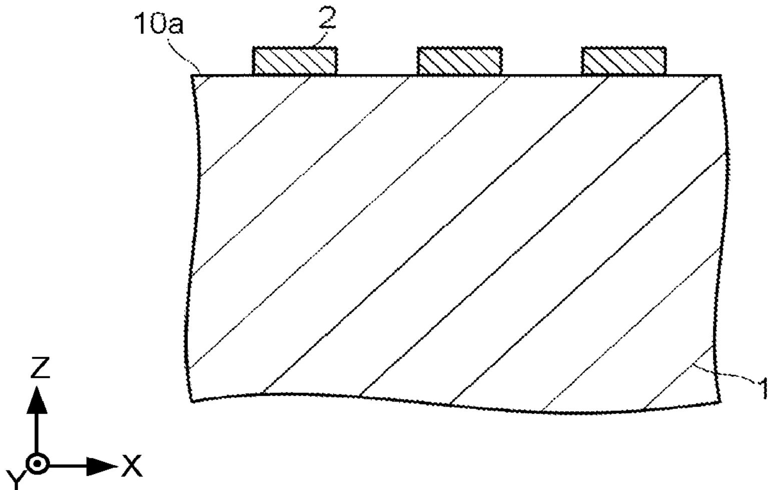


FIG. 7

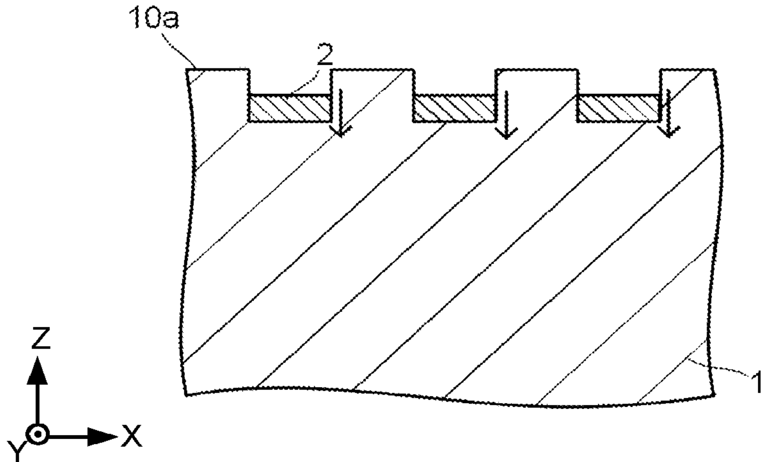


FIG. 8

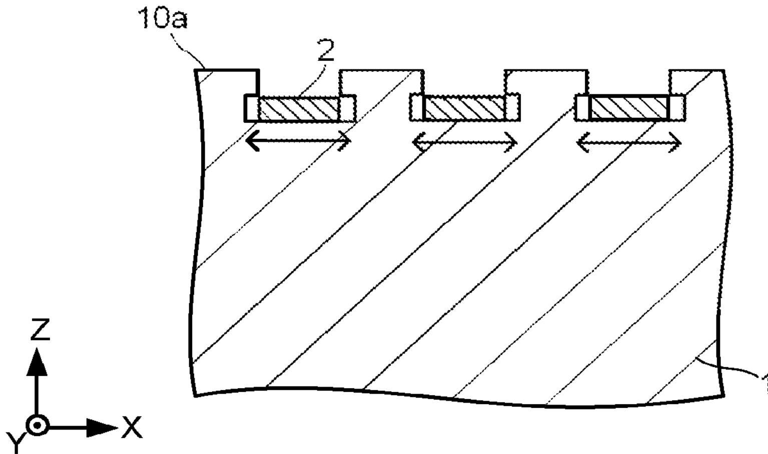


FIG. 9

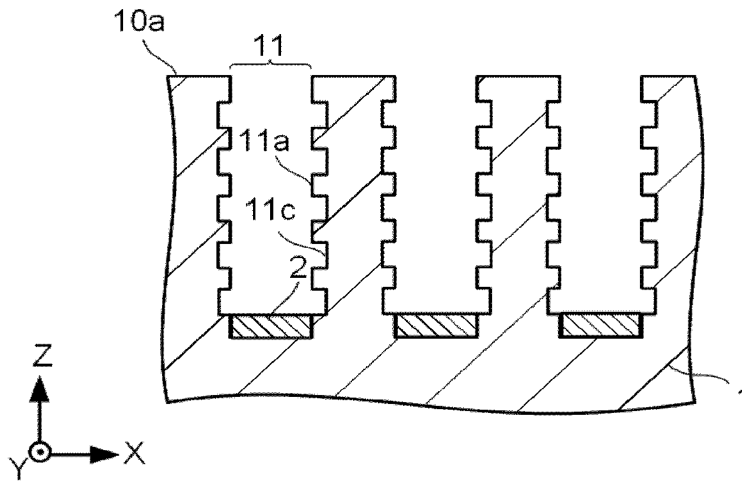


FIG. 10

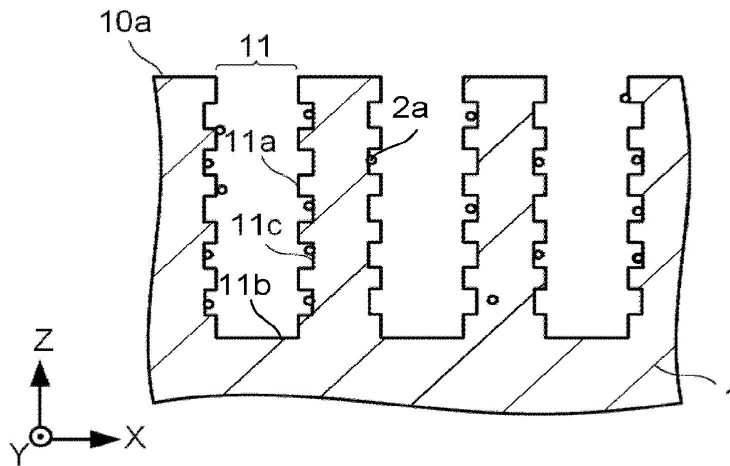


FIG. 11

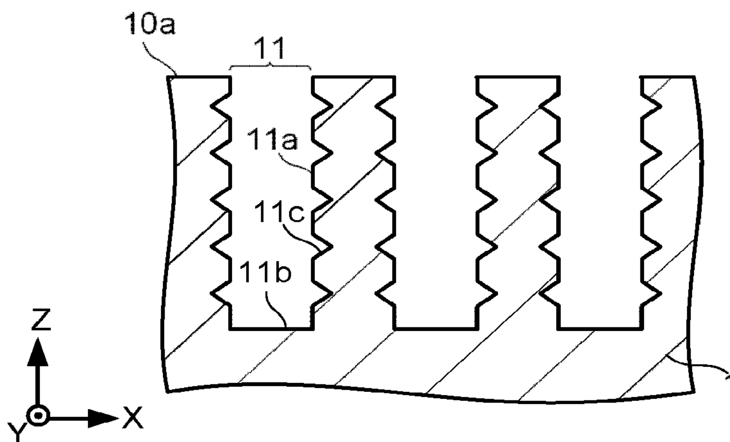


FIG. 12

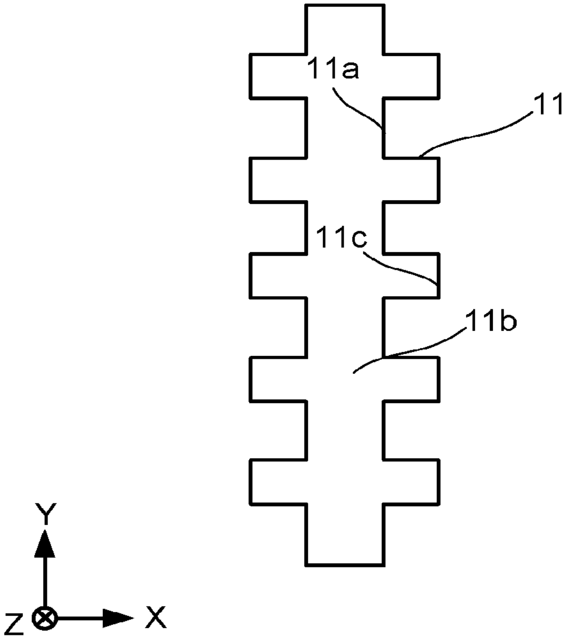


FIG. 13

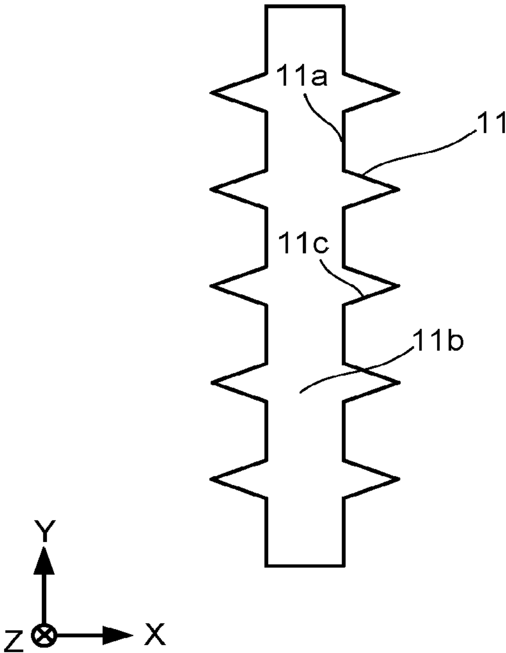


FIG. 14

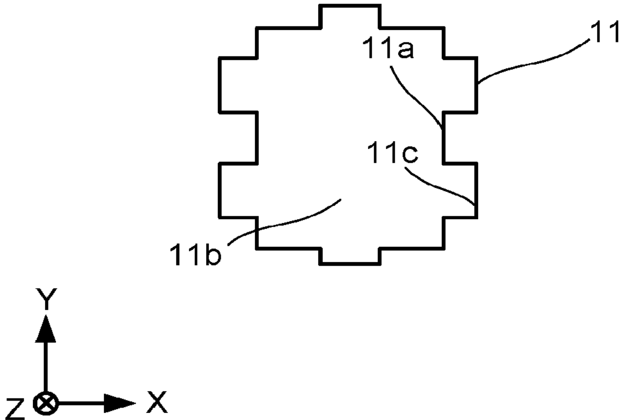


FIG. 15

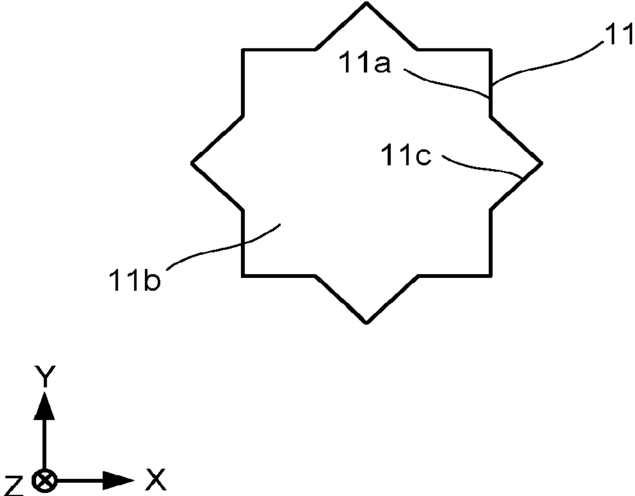


FIG. 16

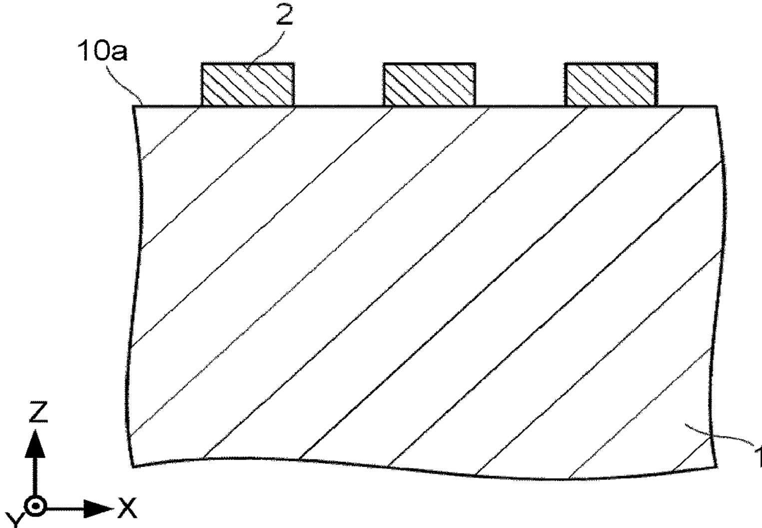


FIG. 17

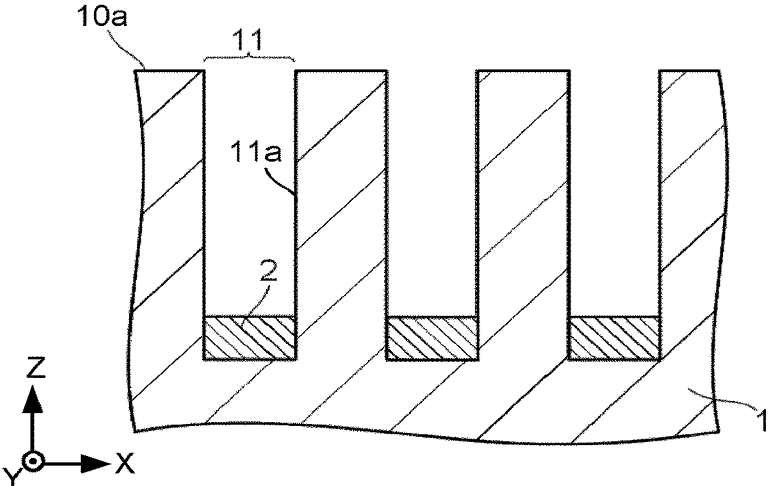


FIG. 18

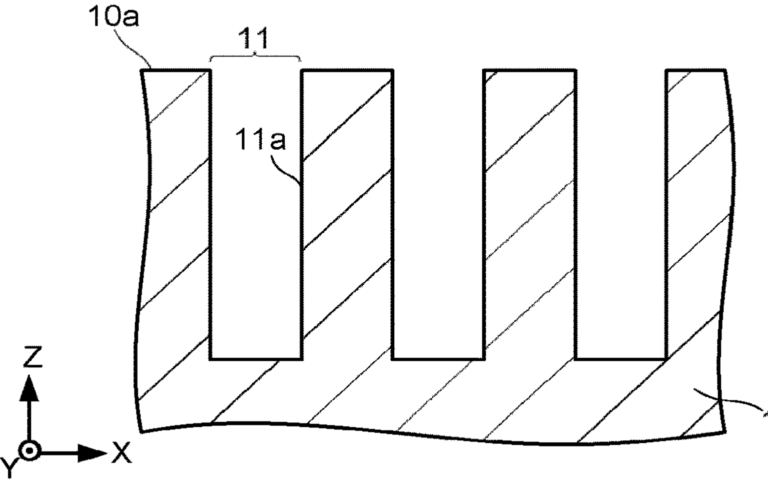


FIG. 19

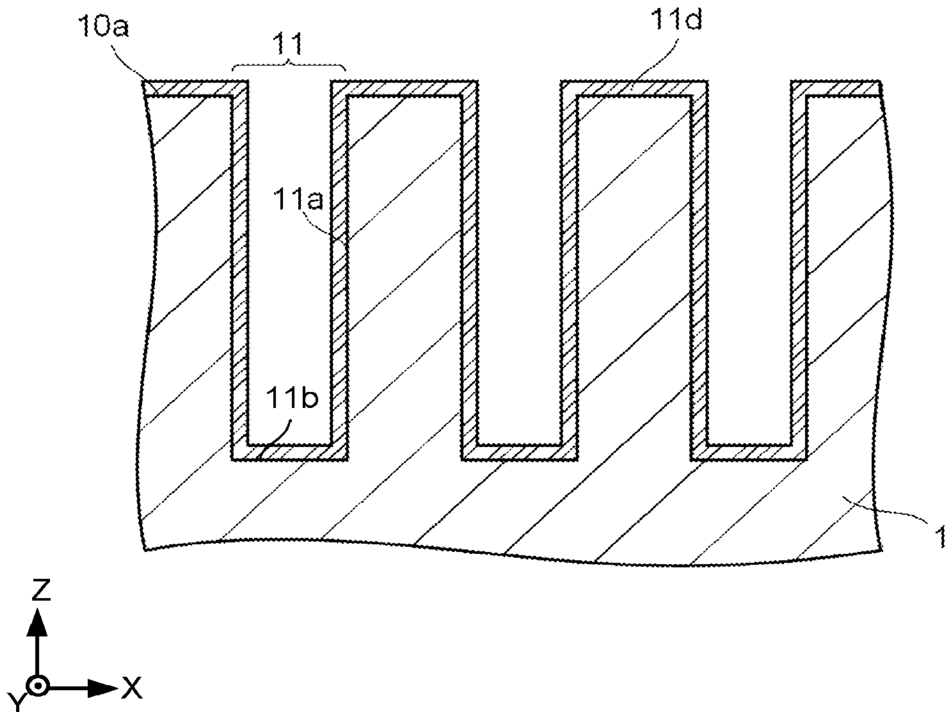


FIG. 20

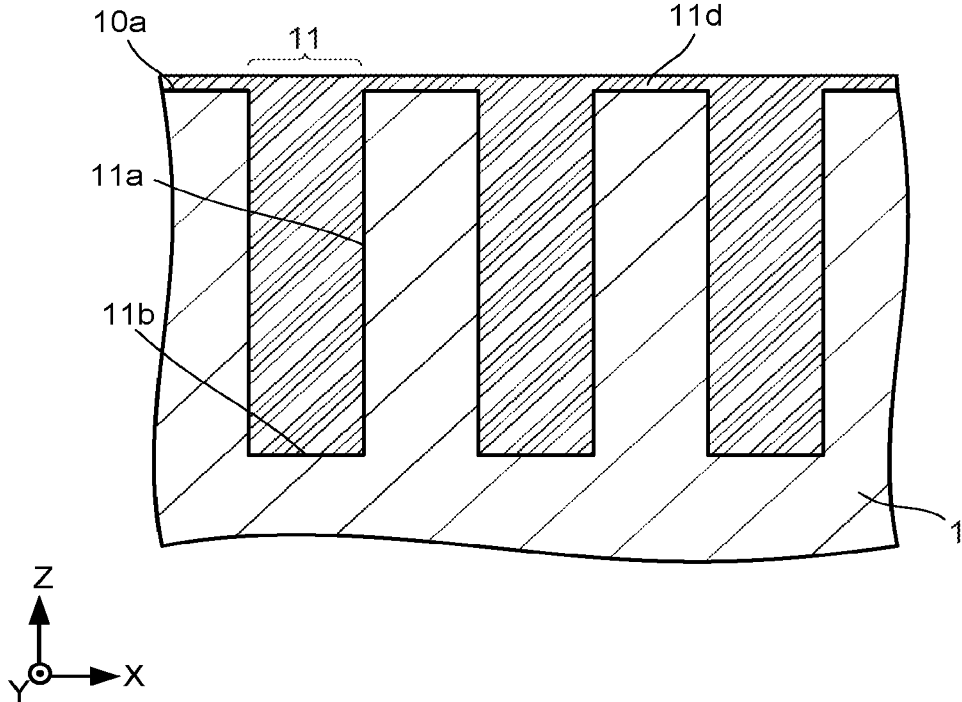


FIG. 21

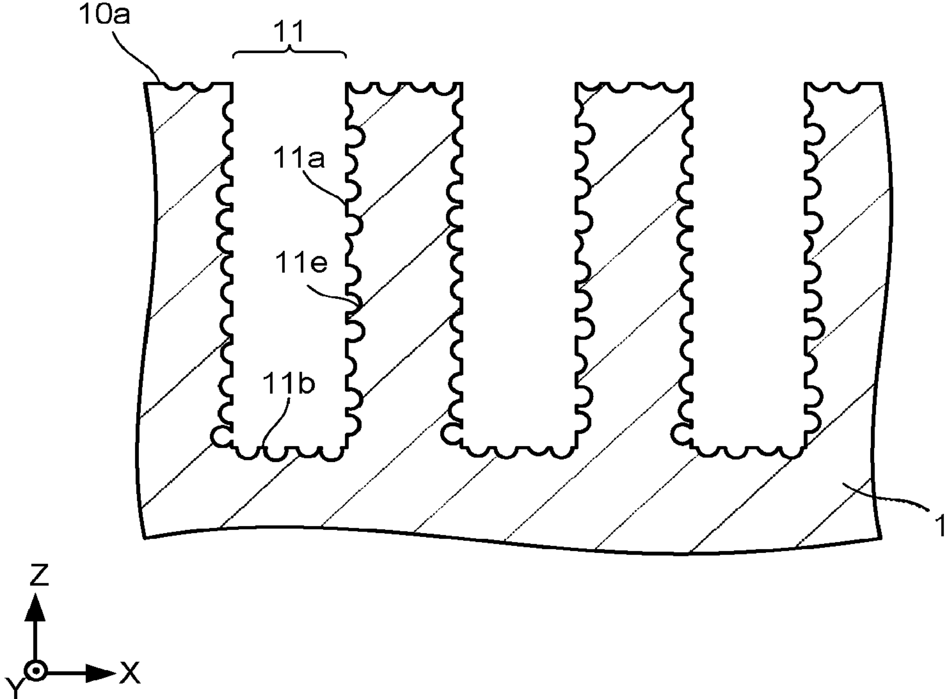


FIG. 22

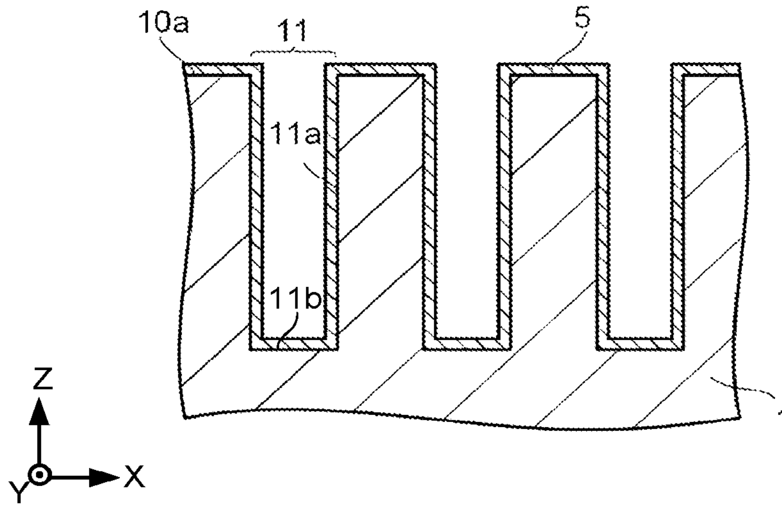


FIG. 23

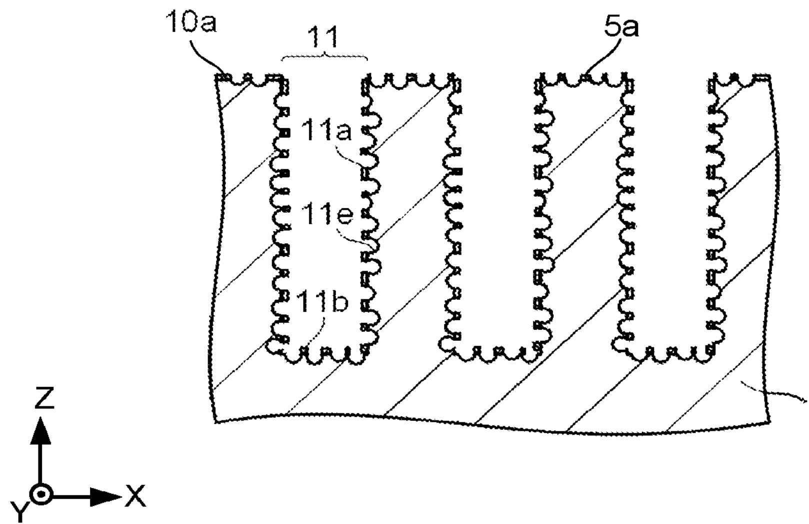
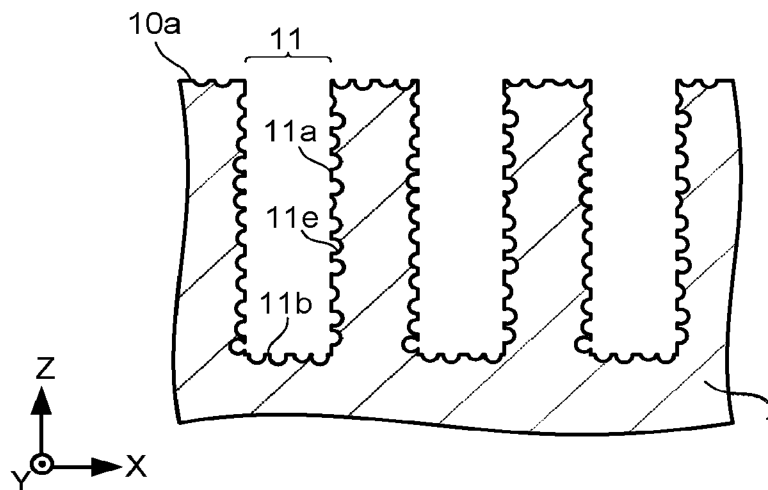


FIG. 24



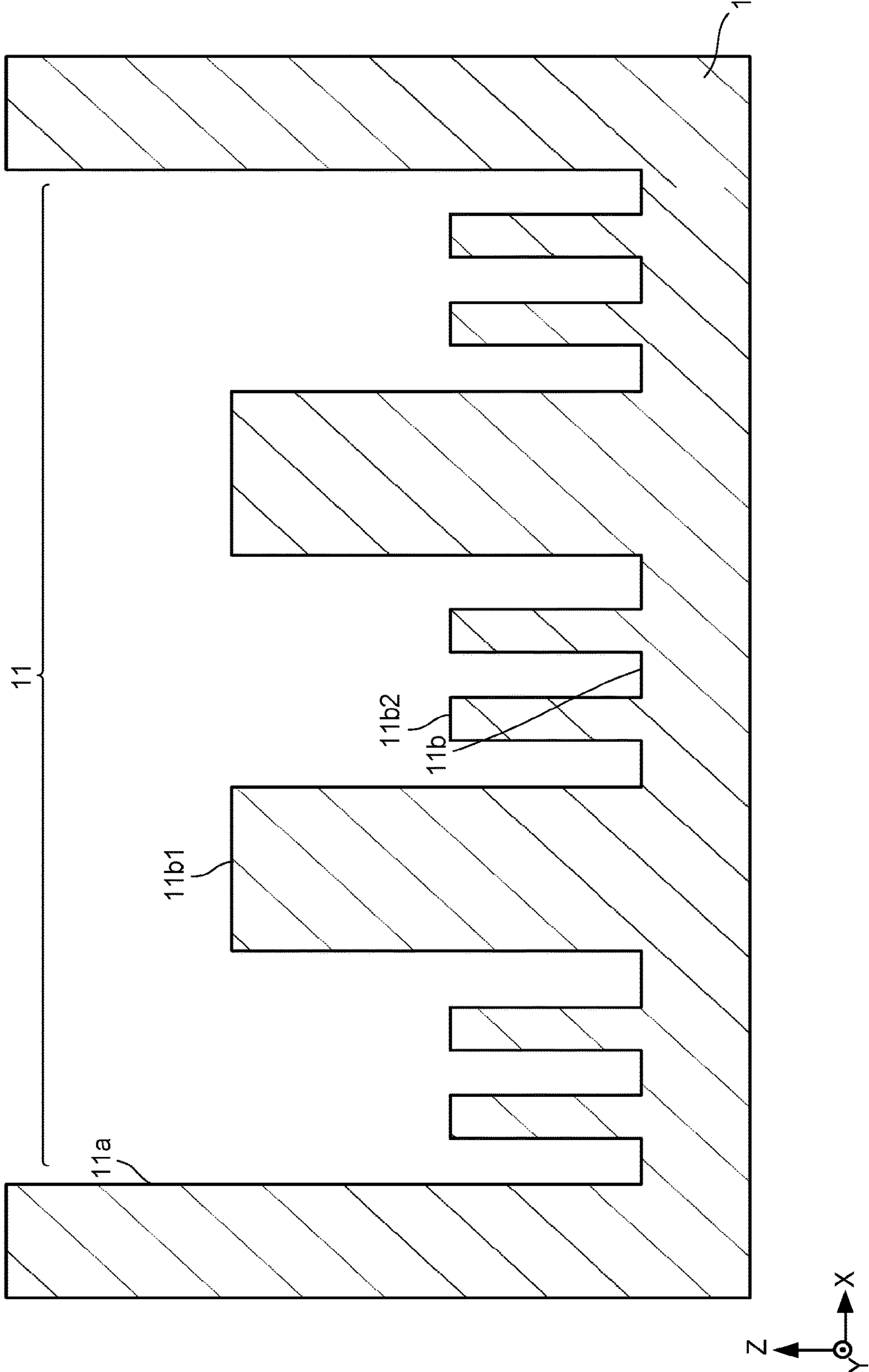


FIG. 25
1
11
11a
11b1
11b2
11b
X
Z
Y

FIG. 26

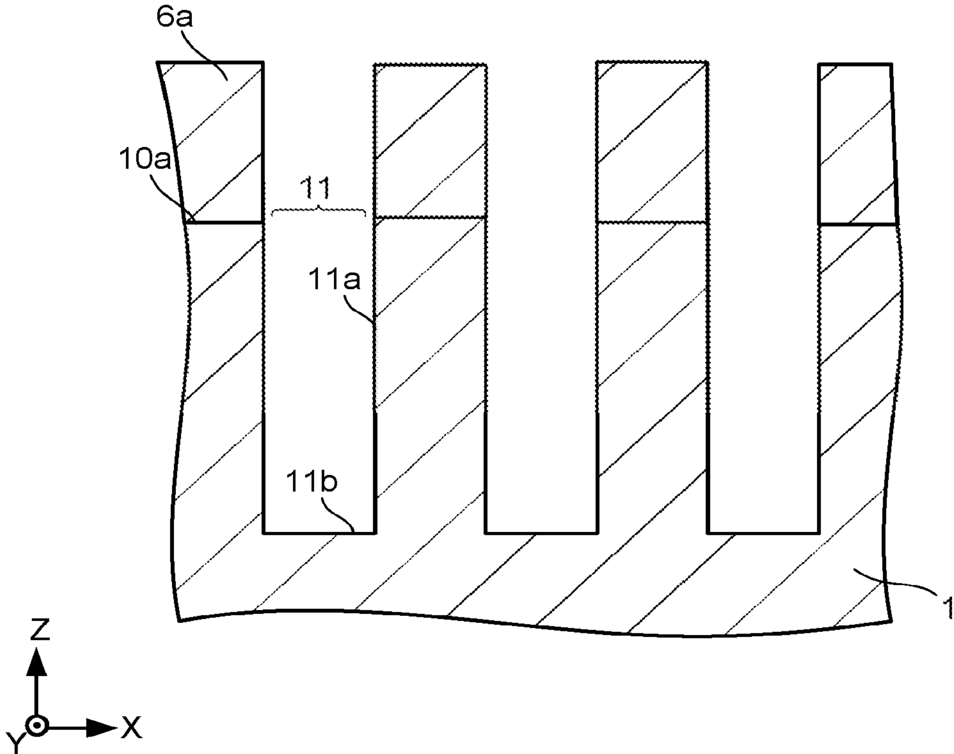


FIG. 27

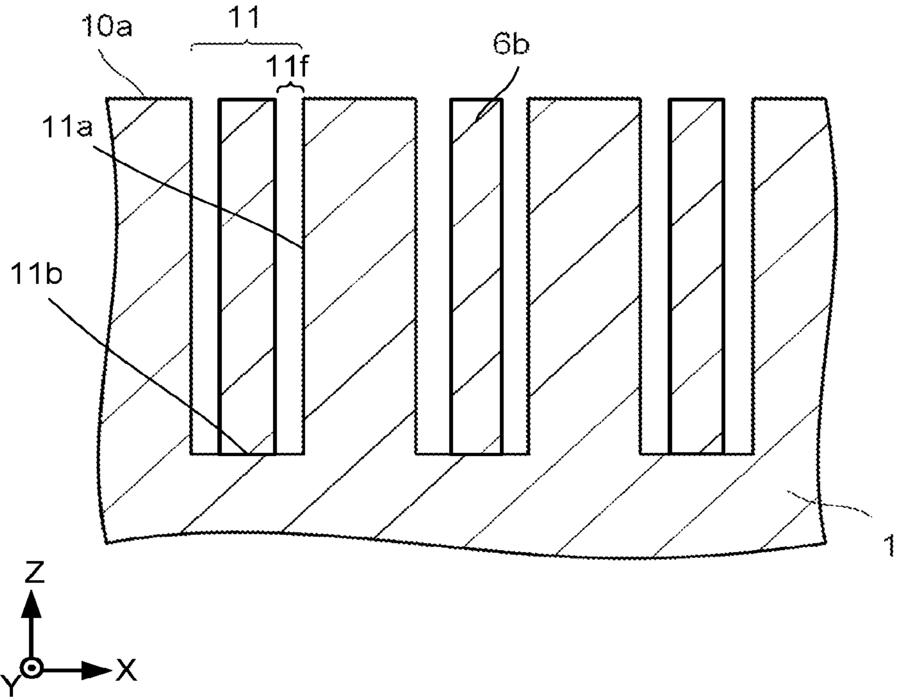


FIG. 28

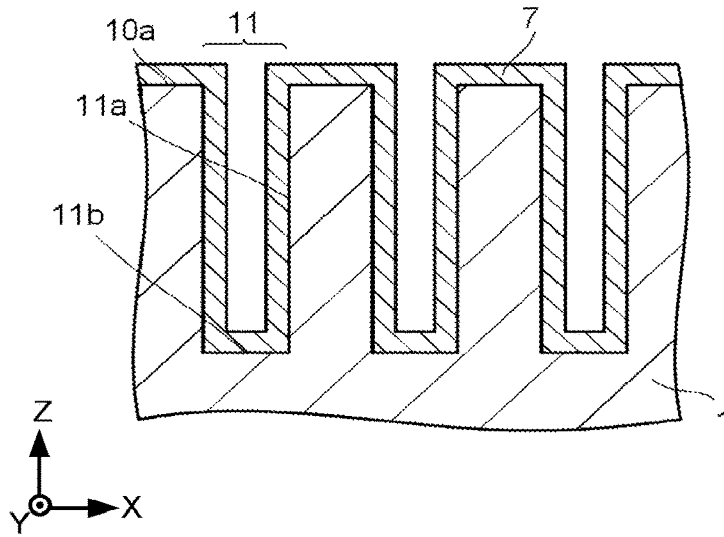


FIG. 29

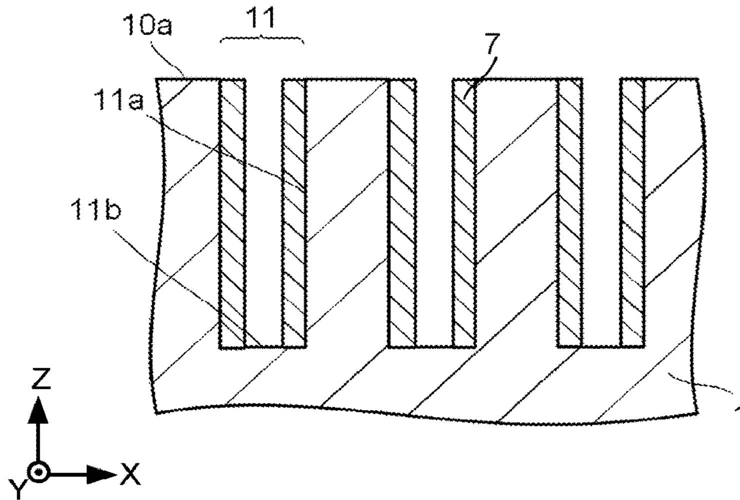


FIG. 30

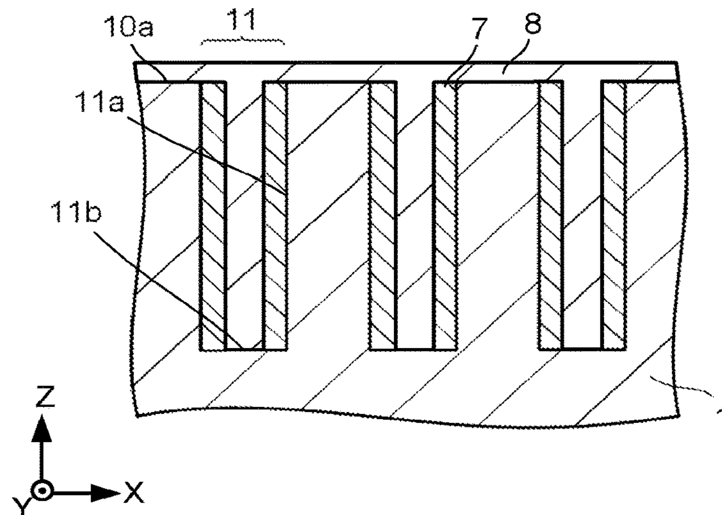


FIG. 31

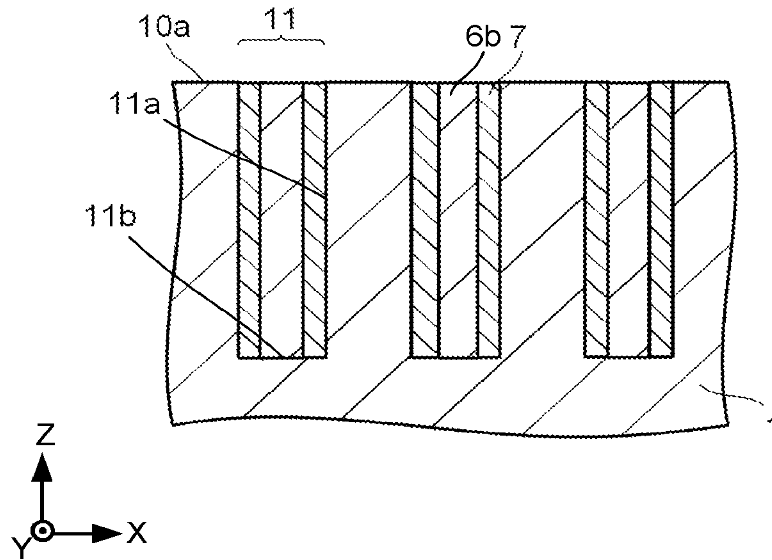


FIG. 32

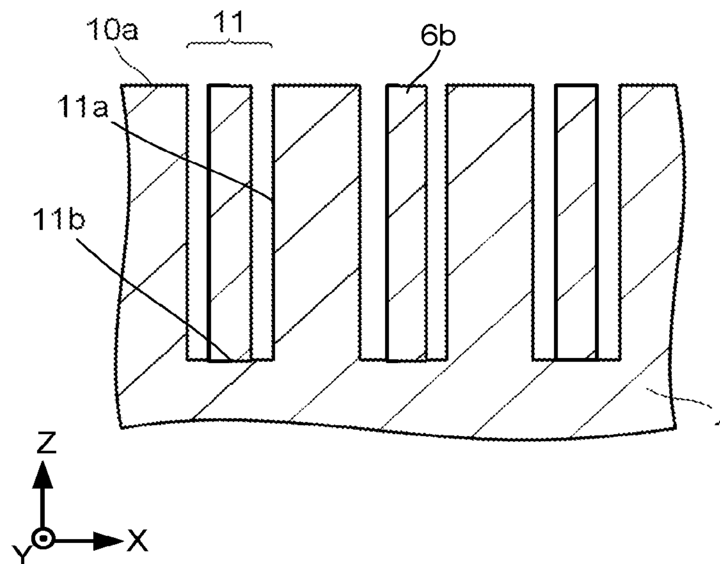


FIG. 33

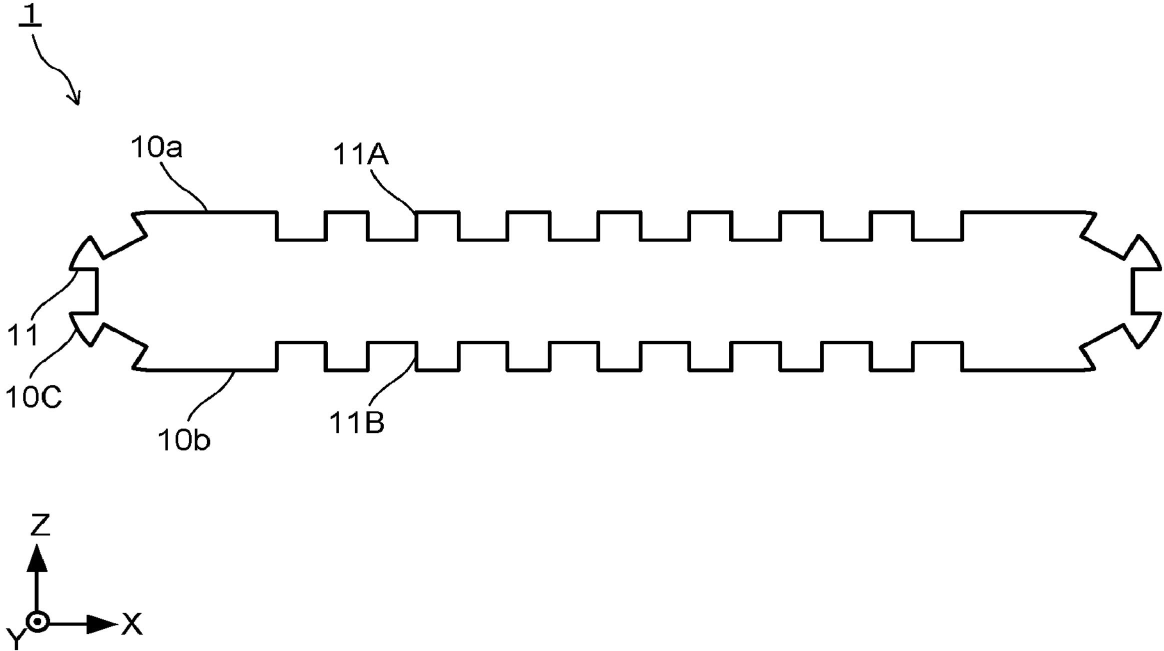


FIG. 34

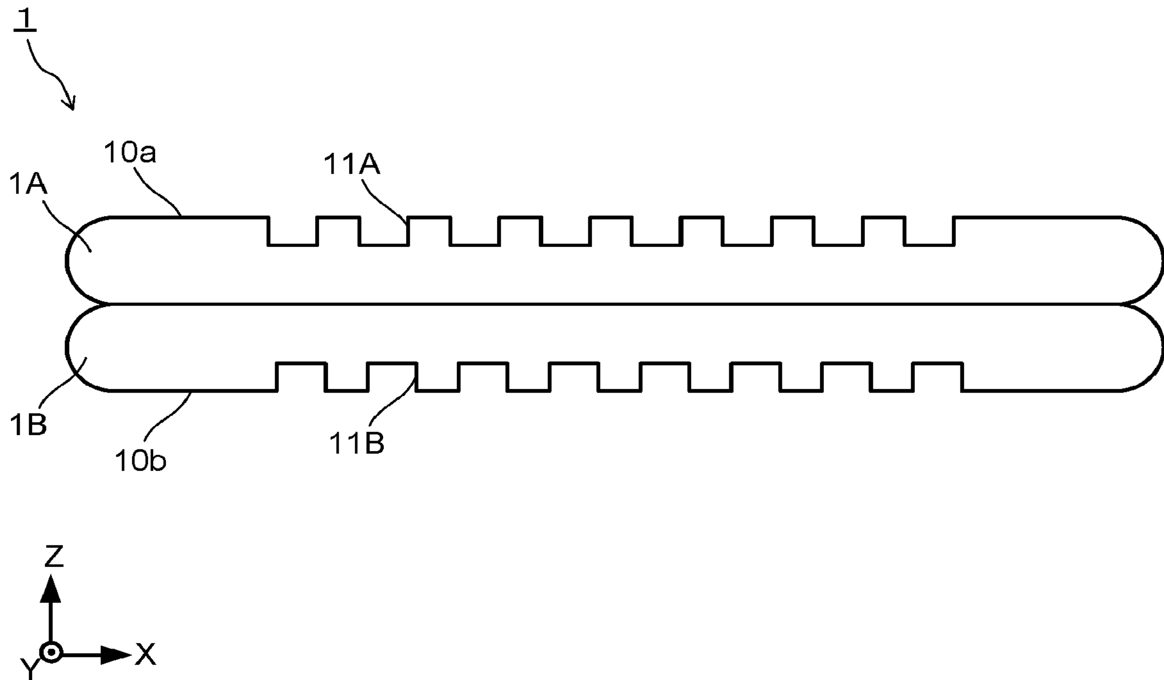


FIG. 35

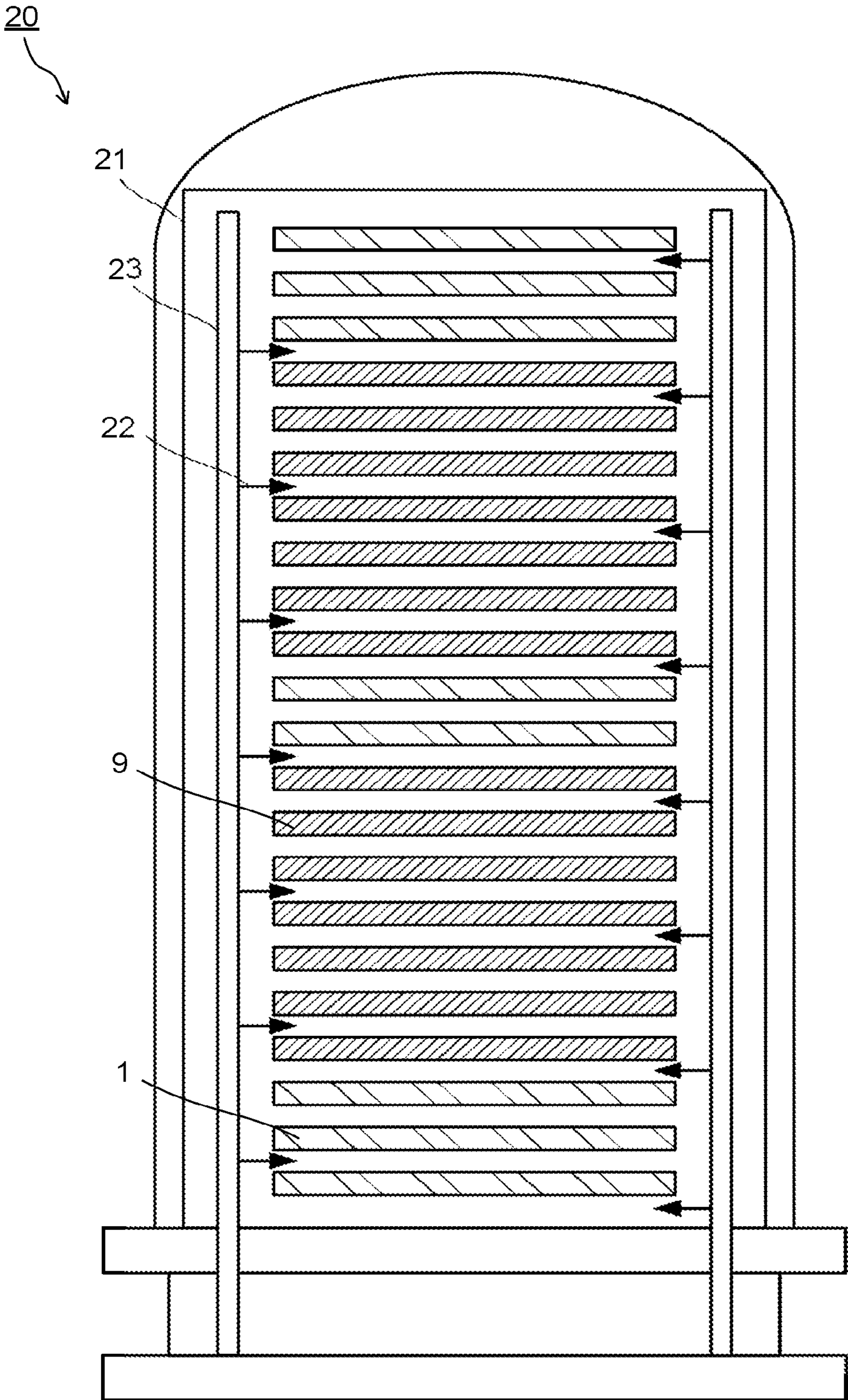


FIG. 36

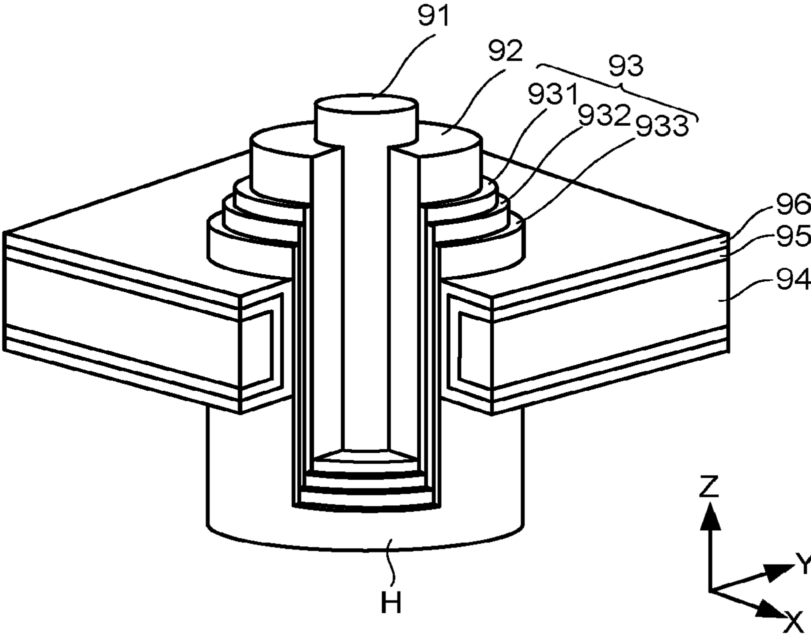


FIG. 37

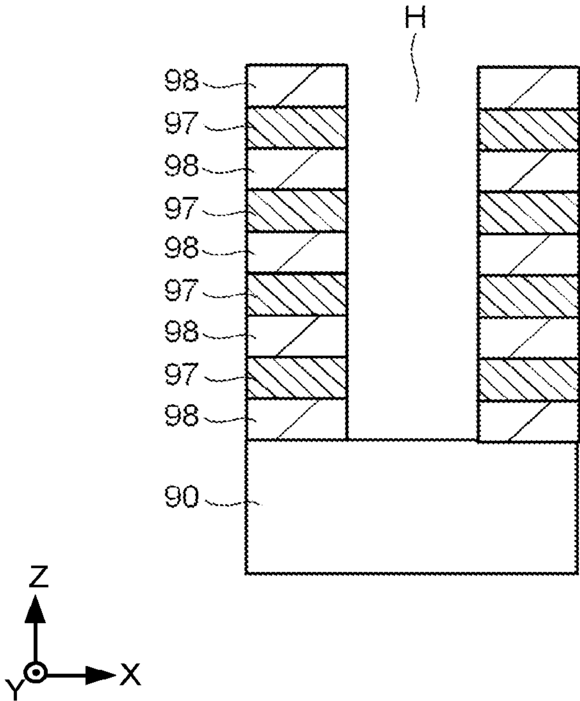


FIG. 38

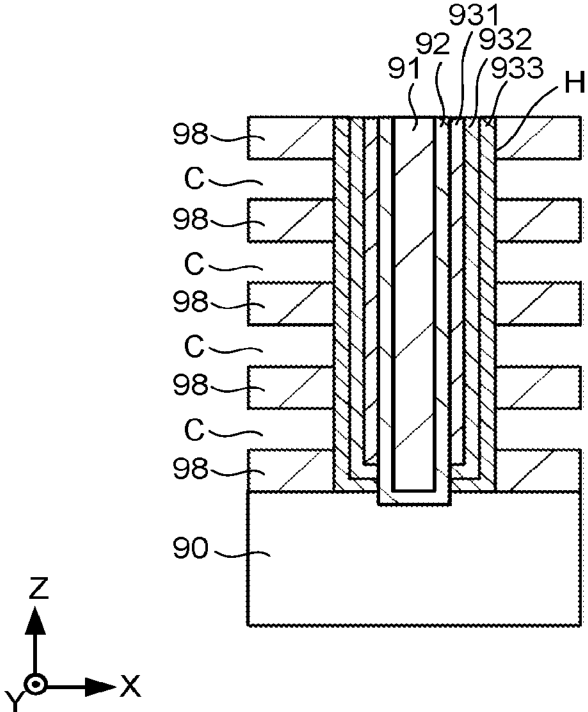
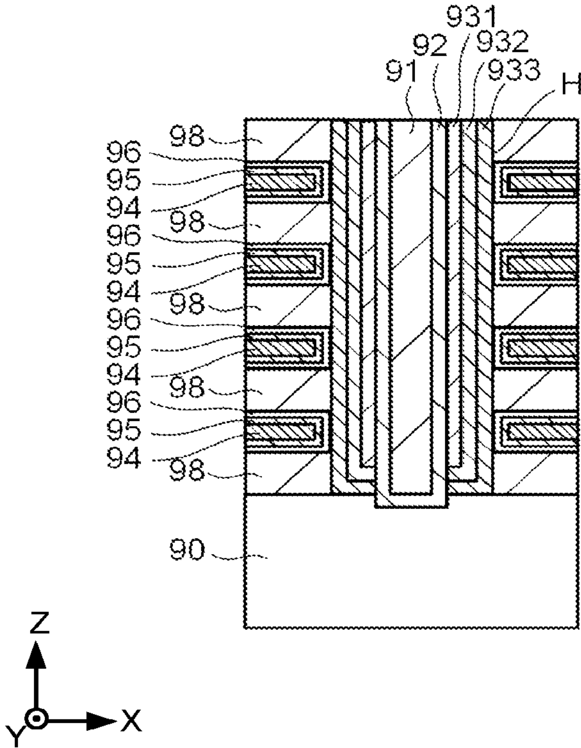


FIG. 39



SEMICONDUCTOR SUBSTRATE, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, AND METHOD OF MANUFACTURING SEMICONDUCTOR SUBSTRATE

CROSS-REFERENCE TO RELATED APPLICATION

This application is based upon and claims the benefit of priority from Japanese Patent Application No. 2020-154443, filed on Sep. 15, 2020; the entire contents of which are incorporated herein by reference.

FIELD

Embodiments relate to a semiconductor substrate, a method of manufacturing a semiconductor device, and a method of manufacturing a semiconductor substrate.

BACKGROUND

Some semiconductor products are manufactured using a Non Product Wafer (NPW) on which a semiconductor device is not formed. A known example of the semiconductor device is formed by three-dimensionally arranging a memory cell on a semiconductor wafer.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. **1** is a schematic view of an external appearance of a semiconductor wafer.

FIG. **2** is a schematic sectional view illustrating a structural example of a semiconductor wafer.

FIG. **3** is a schematic upper view illustrating a structural example of a semiconductor wafer.

FIG. **4** is a schematic upper view illustrating a structural example of a semiconductor wafer.

FIG. **5** is a schematic upper view illustrating a boundary part between a region **101** and a region **102**.

FIG. **6** is a schematic view for explaining an example of a method of manufacturing a semiconductor wafer.

FIG. **7** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer.

FIG. **8** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer.

FIG. **9** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer.

FIG. **10** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer.

FIG. **11** is a schematic sectional view illustrating an example of another shape of a depression **11***c*.

FIG. **12** is a schematic sectional view illustrating an example of another shape of the groove **11**.

FIG. **13** is a schematic sectional view illustrating an example of another shape of the groove **11**.

FIG. **14** is a schematic sectional view illustrating an example of another shape of the groove **11**.

FIG. **15** is a schematic sectional view illustrating an example of another shape of the groove **11**.

FIG. **16** is a view for explaining an example of a method of manufacturing a semiconductor wafer **1** including a surface **10***a* including the groove **11** having a shape illustrated in each of FIG. **12** to FIG. **15**.

FIG. **17** is a view for explaining the example of the method of manufacturing the semiconductor wafer **1** including the surface **10***a* including the groove **11** having the shape illustrated in each of FIG. **12** to FIG. **15**.

FIG. **18** is a view for explaining the example of the method of manufacturing the semiconductor wafer **1** including the surface **10***a* including the groove **11** having the shape illustrated in each of FIG. **12** to FIG. **15**.

FIG. **19** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **20** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **21** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **22** is a schematic view for explaining an example of a method of manufacturing the semiconductor wafer illustrated in FIG. **21**.

FIG. **23** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer illustrated in FIG. **21**.

FIG. **24** is a schematic sectional view illustrating another structural example of the semiconductor wafer illustrated in FIG. **21**.

FIG. **25** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **26** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **27** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **28** is a schematic view for explaining an example of a method of manufacturing the semiconductor wafer illustrated in FIG. **27**.

FIG. **29** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer illustrated in FIG. **27**.

FIG. **30** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer illustrated in FIG. **27**.

FIG. **31** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer illustrated in FIG. **27**.

FIG. **32** is a schematic view for explaining the example of the method of manufacturing the semiconductor wafer illustrated in FIG. **27**.

FIG. **33** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **34** is a schematic sectional view illustrating another structural example of the semiconductor wafer.

FIG. **35** is a schematic view illustrating a configuration example of a semiconductor manufacturing apparatus.

FIG. **36** is a schematic view illustrating a structural example of a semiconductor device.

FIG. **37** is a schematic view for explaining an example a method of manufacturing the semiconductor device.

FIG. **38** is a schematic view for explaining the example the method of manufacturing the semiconductor device.

FIG. **39** is a schematic view for explaining the example the method of manufacturing the semiconductor device.

DETAILED DESCRIPTION

A semiconductor substrate includes a surface having a groove. The groove includes an inner bottom surface and an inner wall surface. The inner wall surface has a depression. The depression has a depth from a direction along a surface of the inner wall surface to a width direction of the groove. The substrate being exposed to the inner wall surface.

Embodiments will be hereinafter described with reference to the drawings. The relation of thickness and planer dimen-

sion of each constituent element, a thickness ratio among the constituent elements, and so on described in the drawings may be different from actual ones. Further, in the embodiments, substantially the same constituent elements are denoted by the same reference signs, and a description thereof will be appropriately omitted.

First Embodiment

FIG. **1** is a schematic view of an external appearance of a semiconductor wafer being a semiconductor substrate, and FIG. **2** is a schematic sectional view illustrating a structural example of a semiconductor wafer, in which a part of an X-Z cross section including an X axis and a Z axis which is orthogonal to the X axis and a Y axis is illustrated. FIG. **3** is a schematic upper view illustrating a structural example of a semiconductor wafer, in which a part of an X-Y plane including an X axis of the semiconductor wafer and a Y axis which is orthogonal to the X axis is illustrated.

The semiconductor wafer **1** is the NPW, and is a wafer which is used for previously evaluating and measuring film formation, etching, and other various processes when manufacturing a semiconductor. For example, the semiconductor wafer **1** is used for evaluating and measuring a film formation process such as chemical vapor deposition (CVD) in which a source gas is made to react with a wafer surface to form a thin film, and atomic layer deposition (ALD), or an etching process such as chemical dry etching (CDE) in which plasma is supplied to a wafer surface to perform etching on a film, atomic layer etching (ALE) in which a source gas is supplied to a surface to perform etching on a film, and wet etching in which liquid is supplied to perform etching on a film. Alternatively, the semiconductor wafer **1** is also used for reproducibility tests for the processes, and the like. Alternatively, the semiconductor wafer **1** is sometimes processed in a processing chamber same as that of a wafer having a semiconductor device formed thereon. The semiconductor wafer **1** can also be referred to as a dummy wafer, a test piece, or the like.

The semiconductor wafer **1** includes a surface **10***a* extending in the X axis direction and the Y axis direction, and a surface **10***b* being an opposite surface of the surface **10***a*. A surface area of the surface **10***a* is preferably about the same as a surface area of a device formation surface of a semiconductor wafer on which a semiconductor device is already formed or in the middle of the formation. Examples of the semiconductor wafer **1** include a silicon wafer, a silicon carbide wafer, a glass wafer, a quartz wafer, a sapphire wafer, a compound semiconductor wafer such as a GaAs substrate, and the like. A shape of the semiconductor wafer **1** is not limited to the shape illustrated in FIG. **1**, and it may be one having an orientation flat, for example.

The surface **10***a* has a pattern including at least one groove **11**. The groove **11** includes an inner wall surface **11***a* and an inner bottom surface **11***b*. The semiconductor wafer **1** is exposed to the inner wall surface **11***a* and the inner bottom surface **11***b*. When plural grooves **11** are provided, the plural grooves **11** are arranged side by side along the X axis direction of the surface **10***a* as illustrated in FIG. **2**, and are extended in a line shape along the Y axis direction of the surface **10***a*. A length L of the groove **11** in a long-side direction is 4 μm or more, for example, and is preferably 40 μm or more. An interval between the grooves **11** which are adjacent along the X axis direction is 0.4 μm or more and 14 μm or less, for example, and is preferably 1 μm or less. End

portions of the grooves **11** which are adjacent along the X axis direction may be displaced from each other along the Y axis direction.

The shape of the groove **11** is not limited to the line shape. The shape of the groove **11** may also be a hole shape, for example.

The inner wall surface **11***a* has a depression **11***c*. The depression **11***e* is exposed. Plural depressions **11***c* are spaced along a depth direction of the groove **11**. The depression **11***c* has a depth from a direction along a surface of the inner wall surface **11***a* (Z axis direction) to a width direction of the groove **11** (X axis direction). Specifically, the inner wall surface **11***a* has a concavity/convexity structure along the depth direction. A length of the depression **11***c* in the Z axis direction (a width of the depression **11***c*) is, for example, 100 nm or more and 2000 nm or less. A length of the depression **11***c* in the X axis direction (a depth of the depression **11***c*) is, for example, 10 nm or more and 200 nm or less.

An aspect ratio of the groove **11** is 50 or more and 1750 or less, for example. The aspect ratio is defined by a ratio of a depth D of the groove **11** to a width W of the groove **11** illustrated in FIG. **3**. The width W of the groove **11** is, for example, 0.4 μm or more and 14 μm or less. The depth D of the groove **11** is, for example, 20 μm or more and a thickness of the semiconductor wafer **1** or less, and the groove **11** may penetrate the wafer **1**. A surface area of the surface **10***a* is, for example, 50 times or more, and preferably 100 times or more a surface area in a case where the groove **11** is not formed. Specifically, it can be said that when the groove or the like is not formed on the surface **10***b*, the surface area of the surface **10***a* is 50 times or more, and preferably 100 times or more a surface area of the surface **10***b*.

It is preferable that the groove **11** has the depth D from the surface **10***a* of 20 μm or more and the aspect ratio of 50 or more, for example. This makes it possible to increase the surface area of the surface **10***a*, and to realize the groove **11** with which a film formed on the surface **10***a* is easily removed.

The groove **11** may also be formed via a partition wall **12**. When the length L, the depth D, and the aspect ratio of the groove **11** become large, the groove **11** is likely to collapse to deform. In contrast to this, by providing the partition wall **12**, the partition wall **12** functions as a beam, which enables to support the groove **11**, and thus it is possible to suppress the deformation of the groove **11**.

In order to suppress the deformation of the groove **11**, the partition wall **12** is preferably provided at intervals of 100 μm or more, for example, in the Y axis direction. Further, lengths of plural partition walls **12** in the Y axis direction are preferably the same. Besides, it is possible that positions of the partition walls **12** between the grooves **11** adjacent in the X axis direction, are displaced to each other along the Y axis direction and regions between the adjacent grooves **11** are connected via the partition wall **12**, as illustrated in FIG. **2**.

The groove **11** may also include plural grooves which extend along mutually different directions. FIG. **4** is a schematic upper view illustrating a structural example of the semiconductor wafer **1**, and it illustrates a part of an X-Y plane. The surface **10***a* of the semiconductor wafer **1** illustrated in FIG. **4** includes a region **101** and a region **102**. The region **101** and the region **102** are alternately arranged along the X axis direction and the Y axis direction, for example. An interval between the region **101** and the region **102** is 2 μm or more, for example. FIG. **4** illustrates one shot region, out of plural shot regions formed on the surface **10***a*.

FIG. **5** is a schematic upper view illustrating a boundary part between the region **101** and the region **102**. The region

101 has grooves 111, and the region 102 has grooves 112. The plural grooves 111 are arranged side by side along the X axis direction, and extended along the Y axis direction. The plural grooves 112 are arranged side by side along the Y axis direction, and extended along the X axis direction. The extending direction (the length L direction) of the groove 111 and the extending direction (the length L direction) of the groove 112 are not limited to directions orthogonal to each other, but they may be directions which intersect each other. The groove 111 and the groove 112 are included in the groove 11. Therefore, for the other explanation of the groove 111 and the groove 112, the explanation of the groove 11 can be appropriately cited. The structure of the surface 10*a* described above may also be formed on the surface 10*b*.

As described above, the semiconductor wafer 1 can be used as a test piece on which a film is formed and evaluation is performed thereon. Alternatively, the semiconductor wafer 1 can also be used as a test piece on which a film is formed, etching is then performed and evaluation is performed thereon. At this time, the semiconductor wafer 1 has a pair of surfaces with different surface areas, and a difference in an amount of film formation on the pair of surfaces is large, and thus warpage of the semiconductor wafer 1 is likely to occur. Accordingly, when, tentatively, all of the plural grooves 11 extend in the same direction, a stress is applied in one direction, resulting in that warpage of the semiconductor wafer 1 is likely to be increased. In contrast to this, by making the plural grooves 11 extend in plural directions, it is possible to suppress the warpage of the semiconductor wafer 1 by dispersing the directions in which the stress is applied.

The semiconductor wafer 1 can be repeatedly used as the test piece. Specifically, it is also possible to continuously perform a film formation step on the semiconductor wafer 1, or continuously perform a film formation step and an etching step on the semiconductor wafer 1. The surface area becomes large because of the depressions 11*c* provided to the inner wall surface 11*a* of the groove 11, so that even when the film formation is continuously performed, it is possible to suppress the change in the surface area, and even when the etching is performed, it is easy to remove a film.

The surface 10*a* may further have a region 103, as illustrated in FIG. 4. The region 103 is preferably a flat surface having no groove 11. Since the region 103 is the flat surface, it is possible to measure, at the region 103, a thickness, a density, and a composition of a film to be formed on the surface 10*a*, for example, by using a measuring device such as a spectral ellipsometer, an X-ray photoelectron spectroscopy (XPS), a fluorescent X-ray analysis, or a Fourier transform infrared spectrophotometer (FTIR) with a minimum measurement region larger than a flat part provided between the grooves 11. An area of the region 103 may be smaller than an area of the region 101 or an area of the region 102, for example. The region 103 is formed for each of plural shot regions of the surface 10*a*, for example.

As described above, by controlling the shape of the groove for increasing the surface area, the semiconductor wafer 1 can realize the groove 11 which is difficult to be deformed. Accordingly, it is possible to suppress the change in the surface area when repeatedly using the semiconductor wafer 1. It is possible to provide a semiconductor wafer having a larger surface area. The dimension of the groove 11 described above is preferably set according to the type and the film thickness of the film to be formed.

The semiconductor wafer 1 can be manufactured by using Metal-assisted Chemical Etching (MACE), for example. The MACE is a technique in which a substrate having a catalyst layer formed on a surface thereof is immersed in a chemical solution, to thereby perform etching only on a region which is brought into contact with the catalyst layer.

FIG. 6 to FIG. 10 are views for explaining an example of a method of manufacturing a semiconductor wafer. The example of the method of manufacturing the semiconductor wafer includes a catalyst layer formation step, an etching step, and a catalyst layer removal step.

In the catalyst layer formation step, a catalyst layer 2 is formed on the surface 10*a* of the semiconductor wafer 1, as illustrated in FIG. 6. The catalyst layer 2 contains a catalyst of noble metal such as, for example, gold, silver, platinum, iridium, or palladium. The catalyst layer 2 can be formed by using, for example, sputtering, a CVD method, a plating method, or the like. The catalyst layer 2 may also contain a catalyst of a carbon material such as graphene.

In the etching step, the semiconductor wafer 1 is immersed in a first etching solution. As the first etching solution, it is possible to use a mixed solution of hydrofluoric acid and a hydrogen peroxide solution, for example.

When the semiconductor wafer 1 is immersed in the first etching solution, a material (silicon, for example) of the surface 10*a* is dissolved in the etching solution, at a contact portion between the surface 10*a* and the catalyst layer 2. When this reaction repeatedly occurs, the semiconductor wafer 1 is etched almost vertically, as illustrated in FIG. 7.

In addition to that, in the etching step, the semiconductor wafer 1 is immersed in a second etching solution. As the second etching solution, it is possible to use a mixed solution of hydrofluoric acid and a hydrogen peroxide solution, for example.

A concentration of hydrogen fluoride in the second etching solution is lower than a concentration of hydrogen fluoride in the first etching solution. The concentration of hydrogen fluoride in the first etching solution is preferably 5.0 mass % or more and 20.0 mass % or less. The concentration of hydrogen fluoride in the second etching solution is preferably 1.0 mass % or more and 3.0 mass % or less. When the semiconductor wafer 1 is immersed in the second etching solution having the concentration, the material (silicon, for example) of the surface 10*a* is dissolved in the etching solution, at the contact portion between the surface 10*a* and the catalyst layer 2. When this reaction repeatedly occurs, the semiconductor wafer 1 is etched in a substantially parallel manner, as illustrated in FIG. 8.

Further, by alternately switching the MACE using the first etching solution and the MACE using the second etching solution, it is possible to form the groove 11 having the inner wall surface 11*a* and the depressions 11*c*, as illustrated in FIG. 9.

In the catalyst layer removal step, the catalyst layer 2 is removed from the surface 10*a*, as illustrated in FIG. 10. The catalyst layer 2 is removed by impregnating the semiconductor wafer 1 with a chemical solution such as a mixed solution of hydrochloric acid and nitric acid (aqua regia) or the like, for example.

Even when the catalyst layer 2 is removed, a slight amount of catalyst atoms 2*a* contained in the catalyst layer 2 sometimes remains inside or on a surface of the semiconductor wafer 1, as illustrated in FIG. 10. An amount of the catalyst atoms 2*a* with respect to the surface area of the semiconductor wafer 1 after removal of the catalyst layer 2 is, for example, 1×10^{11} atoms/cm^2 or less.

A shape of the depression **11**c is controlled by adjusting parameters such as a size of the catalyst layer **2**, the concentration of hydrogen fluoride in the second etching solution, and an etching time, for example. For instance, FIG. **11** is a schematic sectional view illustrating an example of another shape of the depression **11**c. As illustrated in FIG. **11**, the depression **11**c may also have a V-shape in a cross-sectional view.

As described above, in the present embodiment, by forming the depressions **11**c on the groove **11**, it is possible to increase the surface area of the semiconductor wafer **1**.

Further, by manufacturing the semiconductor wafer **1** through the MACE, even when the depression **11**c is formed, it can be easily formed.

Second Embodiment

In the present embodiment, examples of another shape of the groove **11** will be described. Each of FIG. **12** to FIG. **15** is a schematic view illustrating an example of another shape of the groove **11**, and illustrates a part of an X-Y plane of the semiconductor wafer **1**. The explanation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

The groove **11** illustrated in FIG. **12** has a line shape, and an inner wall surface **11**a of the groove **11** has depressions **11**c. The groove **11** illustrated in FIG. **13** has a line shape, and an inner wall surface **11**a of the groove **11** has V-shaped depressions **11**c in a plan view. The groove **11** illustrated in FIG. **14** has a hole shape, and an inner wall surface **11**a of the groove **11** has depressions **11**c. The groove **11** illustrated in FIG. **15** has a hole shape, and an inner wall surface **11**a of the groove **11** has V-shaped depressions **11**c in a plan view. The respective plural depressions **11**c are arranged with an interval provided therebetween, along an inner periphery of the groove **11**. The inner wall surface **11**a, an inner bottom surface **11**b, and the depressions **11**c are exposed.

FIG. **16** to FIG. **18** are views for explaining an example of a method of manufacturing the semiconductor wafer **1** including the surface **10**a including the groove **11** having a shape illustrated in each of FIG. **12** to FIG. **15**. The example of the method of manufacturing the semiconductor wafer includes a catalyst layer formation step, an etching step, and a catalyst layer removal step.

In the catalyst layer formation step, a catalyst layer **2** is formed on the surface **10**a of the semiconductor wafer **1**, as illustrated in FIG. **16**. The catalyst layer **2** contains a catalyst of noble metal such as, for example, gold, silver, platinum, iridium, or palladium. The catalyst layer **2** can be formed by using, for example, sputtering, a CVD method, a plating method, or the like. The catalyst layer **2** may also contain a catalyst of a carbon material such as graphene.

In the etching step, the semiconductor wafer **1** is immersed in an etching solution. As the etching solution, it is possible to use a mixed solution of hydrofluoric acid and a hydrogen peroxide solution, for example.

When the semiconductor wafer **1** is immersed in the etching solution, a material (silicon, for example) of the surface **10**a is dissolved in the etching solution, at a contact portion between the surface **10**a and the catalyst layer **2**. When this reaction repeatedly occurs, the semiconductor wafer **1** is etched almost vertically, as illustrated in FIG. **17**.

In the catalyst layer removal step, the catalyst layer **2** is removed from the surface **10**a, as illustrated in FIG. **18**. The catalyst layer **2** is removed by impregnating the semiconductor wafer **1** with a chemical solution such as aqua regia, for example.

Even when the catalyst layer **2** is removed, a slight amount of catalyst atoms **2**a contained in the catalyst layer **2** sometimes remains inside or on a surface of the semiconductor wafer **1**. A surface density of the catalyst atoms **2**a inside and on the surface of the semiconductor wafer **1** after removal of the catalyst layer **2** is, for example, 1×10^{11} atoms/cm^2 or less.

The depression **11**c having the shape as illustrated in each of FIG. **12** to FIG. **15** can be formed by performing etching on the semiconductor wafer **1** by using the catalyst layer **2** having a planar shape processed in a desired shape. Similarly to the first embodiment, the depressions **11**c having a cross-sectional shape as illustrated in FIG. **2** may be formed by alternately switching the MACE using the first etching solution and the MACE using the second etching solution.

By manufacturing the semiconductor wafer **1** by using the MACE as described above, even when the groove **11** having a large depth D and a large aspect ratio is formed, it can be formed easily.

As described above, in the present embodiment, by forming the depressions **11**c on the groove **11**, it is possible to increase the surface area of the semiconductor wafer **1**.

The present embodiment can be appropriately combined with another embodiment.

Third Embodiment

In the present embodiment, other structural examples of the semiconductor wafer **1** will be described. Each of FIG. **19** and FIG. **20** is a schematic sectional view illustrating another structural example of the semiconductor wafer **1**, and illustrates a part of an X-Z cross section. The explanation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

The semiconductor wafer **1** illustrated in FIG. **19** includes a groove **11** provided on a surface **10**a, and having an inner wall surface **11**a and an inner bottom surface **11**b, and a porous region **11**d provided to face the inner wall surface **11**a and the inner bottom surface **11**b. The porous region **11**d is exposed. A shape of the groove **11** is not particularly limited, but explanation will be made here as a line-shaped groove.

The porous region **11**d is a porous film such as, for example, a silicon oxide film or a silicon oxide film containing doped carbon, and has a large number of pores in the film. An average diameter of the pores is 0.5 nm or more, for example. These porous films can be formed on the surface **10**a through a coating method or a CVD method, for example, after forming the groove **11** on the semiconductor wafer **1** by a method similar to that of the second embodiment. The porous region **11**d does not always have to have a film shape.

A shape of the porous region **11**d changes depending on conditions such as a thickness of film and a forming method. FIG. **20** is a schematic sectional view illustrating an example of another shape of the porous region **11**d. As illustrated in FIG. **20**, it is also possible to fill the groove **11** with the porous region **11**d.

As described above, in the present embodiment, the groove **11** is formed on the semiconductor wafer **1**, and then the porous region **11**d is further formed on the groove **11**, which enables to increase the surface area of the semiconductor wafer **1**.

The present embodiment can be appropriately combined with another embodiment.

Fourth Embodiment

In the present embodiment, another structural example of the semiconductor wafer **1** will be described. FIG. **21** is a schematic sectional view illustrating another structural example of the semiconductor wafer **1**, and illustrates a part of an X-Z cross section. The explanation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

The semiconductor wafer **1** illustrated in FIG. **21** includes a groove **11** provided on a surface **10***a*, and having an inner wall surface **11***a* and an inner bottom surface **11***b*, and a porous region **11***e* that faces the inner wall surface **11***a* and the inner bottom surface **11***b*. The inner wall surface **11***a*, the inner bottom surface **11***b*, and the porous region **11***d* are exposed. A shape of the groove **11** is not particularly limited, but explanation will be made here as a line-shaped groove.

The porous region **11***e* is a porous surface provided to the inner wall surface **11***a* and the inner bottom surface **11***b*. A surface of the porous surface has plural depressions (holes). The plural holes have an average diameter of 5 nm or more and 100 nm or less, and extend along the X axis direction, for example. At least one of the plural holes may penetrate from one of the plural grooves **11** to another groove **11** among the plural grooves **11**.

FIG. **22** to FIG. **24** are views for explaining an example of a method of manufacturing the semiconductor wafer illustrated in FIG. **21**. The example of the method of manufacturing the semiconductor wafer includes a first catalyst layer formation step, a first etching step, a first catalyst layer removal step, a second catalyst layer formation step, a second etching step, and a second catalyst layer removal step. The first catalyst layer formation step, the first etching step, and the first catalyst layer removal step are the same as the catalyst layer formation step, the etching step, and the catalyst layer removal step, respectively, in the second embodiment, and thus explanations thereof will be omitted here.

In the second catalyst layer formation step, a catalyst layer **5** is formed on the surface **10***a* of the semiconductor wafer **1**, as illustrated in FIG. **22**. The catalyst layer **5** contains a catalyst of noble metal such as, for example, gold, silver, platinum, iridium, or palladium. The catalyst layer **5** can be formed by using, for example, sputtering, a CVD method, a plating method, or the like. The catalyst layer **5** may also contain a catalyst of a carbon material such as graphene.

In the second etching step, the MACE is used and the semiconductor wafer **1** is immersed in an etching solution. As the etching solution, it is possible to use a mixed solution of hydrofluoric acid and a hydrogen peroxide solution, for example.

When the semiconductor wafer **1** is immersed in the etching solution, a material (silicon, for example) of the surface **10***a* is dissolved in the etching solution, at a contact portion between the surface **10***a* and the catalyst layer **5**. When this reaction repeatedly occurs, the semiconductor wafer **1** is etched and the porous region **11***e* is formed, as illustrated in FIG. **23**. The surface **10***a* of the etched semiconductor wafer **1** includes a residue **5***a* of the catalyst layer **5**.

In the second catalyst layer removal step, the residue **5***a* of the catalyst layer **5** is removed from the surface **10***a*, as illustrated in FIG. **24**. The catalyst layer **5** is removed by impregnating the semiconductor wafer **1** with a chemical solution such as aqua regia, for example. The porous region **11***e* may be further etched by the chemical solution. At this time, catalyst atoms of the catalyst layer **5** sometimes remain, similarly to the first embodiment.

As described above, in the present embodiment, the groove **11** is formed on the semiconductor wafer **1**, and then the porous region **11***e* is further formed on the groove **11**, which enables to increase the surface area of the semiconductor wafer **1**.

The present embodiment can be appropriately combined with another embodiment.

Fifth Embodiment

In the present embodiment, another structural example of the semiconductor wafer **1** will be described. FIG. **25** is a schematic sectional view illustrating another structural example of the semiconductor wafer **1**, and illustrates a part of an X-Z cross section. The explanation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

A surface **10***a* of the semiconductor wafer **1** illustrated in FIG. **25** includes a groove **11**. For the explanation of the groove **11**, the explanation of the groove **11** of the embodiment can be appropriately cited.

The groove **11** has an inner wall surface **11***a*, an inner bottom surface **11***b*, a protrusion **11***b***1** provided to the inner bottom surface **11***b*, and a protrusion **11***b***2** provided to the inner bottom surface **11***b*. The inner wall surface **11***a* has a height in a direction that intersects the inner bottom surface **11***b* (Z axis direction). Although a planar shape of the groove **11** is not particularly limited, it is a line shape, for example. Although a width of the groove **11** in the X axis direction is not particularly limited, it is 100 μm or more, for example.

The protrusion **11***b***1** extends in the Z axis direction. A height in the Z axis direction of the protrusion **11***b***1** is lower than that of the inner wall surface **11***a*. FIG. **25** illustrates plural protrusions **11***b***1**. Although a planar shape of the protrusion **11***b***1** is not particularly limited, it is a line shape, for example. Although an interval between adjacent protrusions **11***b***1** in the X axis direction is not particularly limited, it is 10 μm or more and less than 100 μm, for example.

The protrusion **11***b***2** extends in the Z axis direction. A height in the Z axis direction of the protrusion **11***b***2** is lower than that of the protrusion **11***b***1**. FIG. **25** illustrates plural protrusions **11***b***2**. The plural protrusions **11***b***2** are provided between the protrusions b**1**. Although a planar shape of the protrusion **11***b***2** is not particularly limited, it is a line shape, for example. Although an interval between adjacent protrusions **11***b***2** in the X axis direction is not particularly limited, it is 1 μm or more and less than 10 μm, for example.

Each of the groove **11**, the protrusion **11***b***1**, and the protrusion **112** can be formed by using the MACE, similarly to the second embodiment, for example. For instance, a first groove can be formed through the MACE using the catalyst layer **2** having a first width, a second groove can be formed on an inner bottom surface of the first groove through the MACE using the catalyst layer **2** having a second width which is smaller than the first width, and a third groove can be formed on an inner bottom surface of the second groove through the MACE using the catalyst layer **2** having a third width which is smaller than the second width.

As described above, in the present embodiment, by forming the plural protrusions (the protrusion **11***b***1**, the protrusion **11***b***2**) on the groove **11** of the semiconductor wafer **1**, it is possible to increase the surface area of the semiconductor wafer **1**.

The present embodiment can be appropriately combined with another embodiment.

Sixth Embodiment

In the present embodiment, another structural example of the semiconductor wafer **1** will be described. FIG. **26** is a schematic sectional view illustrating another structural example of the semiconductor wafer **1**. The explanation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

The semiconductor wafer **1** illustrated in FIG. **26** includes a surface **10***a* having a groove **11** including an inner wall surface **11***a* and an inner bottom surface **11***b*, and a semiconductor layer **6***a* provided on the surface **10***a*. The inner wall surface **11***a*, the inner bottom surface **11***b*, and the semiconductor layer **6***a* are exposed. A shape of the groove **11** is not particularly limited, but explanation will be made here as a line-shaped groove. The semiconductor layer **6***a* is provided to a region of the surface **10***a*, except for the groove **11**, for example, and extends along the inner wall surface **11***a*.

The semiconductor layer **6***a* is an epitaxial layer formed by causing epitaxial growth of a material (silicon, for example) same as that of the semiconductor wafer **1** on the surface **10***a*, for example. As illustrated in FIG. **26**, there is a case where an interface exists between the semiconductor layer **6***a* and the surface **10***a* of the semiconductor wafer **1**.

As described above, in the present embodiment, the inner wall surface **11***a* can be extended by forming the semiconductor layer **6***a* on the surface **10***a* of the semiconductor wafer **1**, and thus it is possible to increase the surface area of the semiconductor wafer **1**.

The present embodiment can be appropriately combined with another embodiment.

Seventh Embodiment

In the present embodiment, another structural example of the semiconductor wafer **1** will be described. FIG. **27** is a schematic sectional view illustrating another structural example of the semiconductor wafer **1**. The explanation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

The semiconductor wafer **1** illustrated in FIG. **27** includes a surface **10***a* having a groove **11** including an inner wall surface **11***a* and an inner bottom surface **11***b*, and a semiconductor layer **6***b* provided on the surface **10***a*. The inner wall surface **11***a*, a part of the inner bottom surface **11***b*, and the semiconductor layer **6***b* are exposed. A shape of the groove **11** is not particularly limited, but explanation will be made here as a line-shaped groove.

The semiconductor layer **6***b* is provided on a part of the inner bottom surface **11***b*. At this time, there is formed a groove **11***f* between the semiconductor layer **6***b* and the inner wall surface **11***a*.

FIG. **28** to FIG. **32** are views for explaining an example of a method of manufacturing the semiconductor wafer illustrated in FIG. **27**. The example of the method of manufacturing the semiconductor wafer includes a catalyst layer formation step, a first etching step, a catalyst layer removal step, a first film formation step, a second etching step, a second film formation step, a third etching step, and a fourth etching step. The catalyst layer formation step, the first etching step, and the catalyst layer removal step are the same as the catalyst layer formation step, the etching step, and the catalyst layer removal step, respectively, of the second embodiment, and thus explanations thereof will be omitted here.

In the first film formation step, a film **7** is formed on the surface **10***a* of the semiconductor wafer **1**, as illustrated in FIG. **28**. The film **7** is formed on a region of the surface **10** except for the groove **11**, the inner wall surface **11***a*, and the inner bottom surface **11***b*. The film **7** preferably contains a material having a high etching selection ratio with respect to the material of the semiconductor wafer **1**, and it contains a material such as silicon oxide, silicon nitride, or silicon oxynitride, for example. The film **7** can be formed by using sputtering, a CVD method, a plating method, or the like, for example.

In the second etching step, the film **7** is partially etched by an etching method such as reactive ion etching, to thereby expose the region of the surface **10***a* except for the groove **11**, and the inner bottom surface **11***b*, as illustrated in FIG. **29**. A part of the film **7** remains along the inner wall surface **11***a*.

In the second film formation step, a film **8** is formed on the surface **10***a* of the semiconductor wafer **1**, as illustrated in FIG. **30**. The film **8** is formed on the exposed region of the surface **10***a* except for the groove **11**, the film **7**, and the inner bottom surface **11***b*. The film **8** is a silicon film, for example. The film **8** can be formed by using sputtering, a CVD method, a plating method, or the like, for example.

In the third etching step, the film **8** is partially etched by etching such as reactive ion etching or wet etching, to thereby expose an upper end of a residue of the film **7**, and form the semiconductor layer **6**, as illustrated in FIG. **31**.

In the fourth etching step, the residue of the film **7** is etched by an etching method of wet etching or the like, to thereby remove the residue of the film **7** facing the inner wall surface **11***a*, as illustrated in FIG. **32**. Consequently, the semiconductor layer **6***b* can be formed.

As described above, in the present embodiment, the semiconductor layer **6***b* is formed on the surface **10***a* of the semiconductor wafer **1**, to thereby further form the groove **11***f*, which enables to increase the surface area of the semiconductor wafer **1**.

The present embodiment can be appropriately combined with another embodiment.

Eighth Embodiment

In the present embodiment, another structural example of the semiconductor wafer **1** will be described. FIG. **33** is a schematic sectional view illustrating another structural example of the semiconductor wafer **1**. The explanation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

The semiconductor wafer **1** illustrated in FIG. **33** includes a surface **10***a* having a groove **11**A, a surface **10***b* provided on an opposite side of the surface **10***a* and having a groove **11**B, and a bevel surface **10***c* extending from the surface **10***a* or the surface **10***b* and having a groove **11**C. A shape of each of the groove **11**A, the groove **11**B, and the groove **11**C is not particularly limited, but explanation will be made here as a line-shaped groove having exposed inner wall surface and inner bottom surface.

The semiconductor wafer **1** of the present embodiment is not limited to one having the structure illustrated in FIG. **33**. FIG. **34** is a schematic sectional view illustrating another structural example of the semiconductor wafer **1**. The expla-

nation can be appropriately cited for a part same as that of the explanation of the semiconductor wafer **1** described above.

The semiconductor wafer **1** illustrated in FIG. **34** includes a first semiconductor wafer **1**A having a surface **10***a* having a groove **11**A, and a second semiconductor wafer **1**B having a surface **10***b* having a groove **11**B. The first semiconductor wafer **1**A and the second semiconductor wafer **1**B are bonded through thermal bonding, for example. A shape of each of the groove **11**A and the groove **11**B is not particularly limited, but explanation will be made here as a line-shaped groove.

As described above, in the present embodiment, by forming the groove **11** on the plural surfaces, it is possible to increase the surface area of the semiconductor wafer **1**.

The present embodiment can be appropriately combined with another embodiment.

Ninth Embodiment

In the present embodiment, an example in which the semiconductor wafer **1** is used as a dummy wafer in a manufacturing step of a semiconductor device, as an example of a method of using a semiconductor wafer, will be described by using FIG. **35** to FIG. **38**.

FIG. **35** is a schematic view illustrating a configuration example of a semiconductor manufacturing apparatus. FIG. **35** illustrates a configuration example of LP-CVD (Low Pressure Chemical Vapor Deposition) apparatus. A semiconductor manufacturing apparatus **20** illustrated in FIG. **35** includes a processing chamber **21**, and a pipe **23** for supplying a source gas **22** into the processing chamber **21**. The LP-CVD apparatus **20** further includes a vacuum pump, a heater, an exhaust system, a power source, a control circuit, and so on which are not illustrated.

There is a case where the semiconductor wafer **1** as a dummy wafer is conveyed, together with a device wafer **9** being a semiconductor wafer on which a semiconductor device is already formed or in the middle of the formation, into the same processing chamber **21**, and the semiconductor wafer **1** and the device wafer **9** are processed simultaneously. An example of a method of manufacturing the semiconductor device of this case includes a step of placing the device wafer **9** in the processing chamber **21**, a step of placing the semiconductor wafer **1** of the embodiment in the processing chamber **21**, and a step of performing processing on the device wafer **9** and the semiconductor wafer **1** simultaneously in the processing chamber **21**. The device wafer **9** and the semiconductor wafer **1** are placed in the processing chamber **21** through the same step or different steps.

FIG. **35** illustrates an example in which, when plural device wafers **9** are processed in the processing chamber **21**, at least one semiconductor wafer **1** is placed in the processing chamber **21** together with the plural device wafers **9**, and the wafers are subjected to film formation processing simultaneously. Although the number of the semiconductor wafer **1** to be placed is only required to be one or more, it is preferable to place plural semiconductor wafers **1**, as illustrated in FIG. **35**. Further, the semiconductor wafer **1** is preferably arranged at at least an upper region or a lower region in the processing chamber **21**, as illustrated in FIG. **35**.

Here, a structural example of the device wafer **9** will be described. A semiconductor device which is formed on the device wafer **9** is, for example, a three-dimensional NAND-type flash memory. Hereinafter, a film formation step when manufacturing the three-dimensional NAND-type flash memory will be described.

FIG. **36** is a schematic view illustrating a structural example of a semiconductor device. The semiconductor device illustrated in FIG. **36** includes a core insulating film **91**, a semiconductor channel layer **92**, a memory film **93** including a tunnel insulating film **931**, a charge storage layer **932**, and a block insulating film **933**, an electrode material layer **94**, a metal layer **95**, and an insulating layer **96**. The electrode material layer **94** functions as a gate electrode (word line). The core insulating film **91**, the semiconductor channel layer **92**, and the memory film **93** are formed in a memory hole H, and configure a memory cell. The block insulating film **933** is a SiO_2 film (silicon oxide film), for example. The charge storage layer **932** is a SiN film (silicon nitride film), for example. The tunnel insulating film **931** is a stacked film including a SiO_2 film and a SiON film (silicon oxynitride film), for example. The semiconductor channel layer **92** is a polysilicon layer, for example. The core insulating film **91** is a SiO_2 film, for example. The electrode material layer **94**, the metal layer **95**, and the insulating layer **96** are a W layer (tungsten layer), a TiN film (titanium nitride film), and an Al_2O_3 film (aluminum oxide film), respectively, for example. In this case, the metal layer **95** functions as a barrier metal layer in the electrode layer described above, and the insulating layer **96** functions as a block insulating film together with the block insulating film **933**.

Next, an example of a method of manufacturing the semiconductor device illustrated in FIG. **36** will be described by using FIG. **37**, FIG. **38**, and FIG. **39**. In FIG. **37**, a stacked film in which plural sacrificial layers **97** and plural insulating layers **98** are alternately stacked is formed on a semiconductor wafer **90** such as a silicon wafer, and in these sacrificial layers **97** and insulating layers **98**, the memory hole H being a groove is provided. The sacrificial layer **97** is a region in which the electrode material layer is to be formed later. The memory hole H is a region in which the memory film **93** is to be formed later.

The semiconductor wafer **1** is used for forming the memory film **93**, the semiconductor channel layer **92**, and the core insulating film **91**, or forming the electrode material layer **94**, the metal layer **95**, and the insulating layer **96**, and for modification treatment and etching process of those thin films including the sacrificial layers **97** and the insulating layers **98** configuring a side surface of the memory hole H, when manufacturing the semiconductor device, for example.

The formation of the memory film **93** is performed by making the device wafer **9** in a state where, as illustrated in FIG. **37**, the memory hole H is formed in the stack in which the plural sacrificial layers **97** and the plural insulating layers **98** are alternately stacked to be conveyed into the processing chamber **21**, to thereby form the block insulating film **933**, the charge storage layer **932**, and the tunnel insulating film **931** in this order in the memory hole H.

The formation of the metal layer **95** and the insulating layer **96** is performed by making the device wafer **9** on which the memory film **93** is formed and then the plural sacrificial layers are removed to provide a cavity C between the plural insulating layers **98** as illustrated in FIG. **38**, to be conveyed into the processing chamber **21**, to thereby form the insulating layer **96**, the metal layer **95**, and the electrode material layer **94** in this order in the cavity C (this is called a replacement step), as illustrated in FIG. **39**.

The modification treatment includes oxidation caused by performing treatment using gas containing oxygen, nitridation caused by performing gas phase treatment using nitro-

gen-containing gas such as ammonia, and crystallization caused by performing heat treatment after or in the middle of the formation of respective layers or films in the formation step of the sacrificial layers **97** and the insulating layers **98**, the block insulating film **933**, the charge storage layer **932**, the tunnel insulating film, and the semiconductor channel layer **92** in FIG. **37** and FIG. **38**, for example. Further, the modification treatment includes treatment in which a sacrificial layer containing a desired impurity such as boron, phosphorus, or metal is formed after the formation of the layer or film, the impurity is diffused in a targeted layer or film by performing heat treatment, and then the sacrificial layer is etched to be removed. This also applies to the electrode material layer **94**, the metal layer **95**, and the insulating layer **96**.

The etching process includes a process of reducing a thickness of, for example, each of the sacrificial layers **97** and the insulating layers **98** in FIG. **37**, and the formed block insulating film **933**, charge storage layer **932**, tunnel insulating film, and semiconductor channel layer **92** in FIG. **38**, after the formation thereof, by using an etching gas containing halogen such as fluorine, chlorine, or bromine, or the like. The same applies to the electrode material layer **94**, the metal layer **95**, and the insulating layer **96** in FIG. **39**.

In each of the examples, at least one semiconductor wafer **1** is conveyed into the processing chamber **21** together with the plural device wafers **9**, and the similar processing is performed. Consequently, when a desired processing result cannot be obtained at a specific position in the processing chamber **21**, it is possible to use the semiconductor wafer **1** as a dummy wafer. Plural pieces of processing may be performed.

As described above, the semiconductor wafer **1** is formed with the plural grooves **11** so as to increase its surface area. Accordingly, the semiconductor wafer **1** becomes a dummy wafer having a surface area which is about the same as the surface area of the device wafer **9**. Therefore, it is possible to further reduce a variation in film formation in the processing chamber **21** caused by a surface area difference, for example, resulting in that uniformity of the film thickness, the film composition, the film density, and so on between the device wafers **9** or within a plane of the device wafer **9** can be further improved. Specifically, it becomes possible to manufacture a semiconductor device with further improved reliability.

The semiconductor wafer **1** is used as the dummy wafer, so that a purity of semiconductor thereof may be lower than that of the device wafer **9**. Accordingly, the semiconductor wafer **1** may have an electric resistivity lower than that of the device wafer **9**, and it may have an impurity concentration higher than that of the device wafer **9**.

The depth (the length in the Z axis direction) of the groove **11** of the semiconductor wafer **1** is larger than the depth (the length in the Z axis direction) of the memory hole MH formed on the device wafer **9**.

Although the present usage example has been explained by citing the LP-CVD apparatus as an example, the semiconductor wafer **1** can also be applied to another semiconductor manufacturing apparatus. Further, the semiconductor device is not limited to the three-dimensional NAND-type flash memory, and it is also possible to apply another semiconductor device.

While certain embodiments of the present invention have been described, these embodiments have been presented by way of example only, and are not intended to limit the scope of the inventions. The novel embodiments described herein may be embodied in a variety of other forms; furthermore, various omissions, substitutions and changes may be made therein without departing from the spirit of the inventions. The accompanying claims and their equivalents are intended to cover such forms or modifications as would fall within the scope and spirit of the inventions.

Clauses based on the embodiments will be additionally described below.

(Clause 1) A semiconductor substrate, including

a surface having a groove, the groove including an inner bottom surface and an inner wall surface, the inner wall surface having a depression, the depression having a depth from a direction along a surface of the inner wall surface to a width direction of the groove, and

the substrate being exposed to the inner wall surface.

(Clause 2) The substrate according to clause 1, wherein:

the inner wall surface has a plurality of the depressions; and

the depressions are spaced along a depth direction of the groove or along an inner periphery of the groove.

(Clause 3) A semiconductor substrate, including:

a surface having a groove, the groove including an inner bottom surface and an inner wall surface; and

a porous region facing the inner bottom surface and the inner wall surface.

(Clause 4) A semiconductor substrate, including:

an inner bottom surface;

an inner wall surface having a height in a first direction, the first direction intersecting the inner bottom surface; and

a protrusion provided on the inner bottom surface, extending in the first direction, and being lower in a height in the first direction than the inner wall surface,

the substrate being exposed to the inner wall surface.

(Clause 5) The substrate according to clause 1, further including a semiconductor layer partly provided on the surface and extending along the inner wall surface.

(Clause 6) The substrate according to clause 1, further including a second surface provided on an opposite side of the surface and having a second groove, the second groove including a second inner wall surface.

(Clause 7) The substrate according to clause 1, wherein the substrate is a silicon wafer, a silicon carbide wafer, a glass wafer, a quartz wafer, a sapphire wafer, or a compound semiconductor wafer.

(Clause 8) A method of manufacturing a semiconductor device, including:

placing a first semiconductor substrate into a chamber, the first semiconductor substrate including a first surface and a film provided on the first surface, the film having a first groove;

placing a second semiconductor substrate into the chamber, the second semiconductor substrate being the substrate according to clause 1; and processing the first and second semiconductor substrates in the chamber.

(Clause 9) The method according to clause 8, wherein

the film has first layers and second layers, each first layer and each second layer being alternately stacked.

(Clause 10) The method according to clause 8, wherein

the processing includes at least one processing selected from the group consisting of film formation processing, an etching process, and modification treatment.

(Clause 11) The method according to clause 8, wherein

a plurality of the second semiconductor substrates is placed into the chamber.

(Clause 12) A method of manufacturing a semiconductor substrate, including:

forming a catalyst layer onto a surface of a semiconductor substrate;

supplying a first liquid to the substrate with the catalyst layer, the first liquid containing hydrogen fluoride; and

supplying a second liquid to the substrate with the catalyst layer after the supply of the first liquid, the second liquid containing hydrogen fluoride and being lower in a concentration of the hydrogen fluoride than the first liquid.

What is claimed is:

1. A semiconductor substrate, comprising

a surface having a groove, the groove including an inner bottom surface and an inner wall surface, the inner wall surface having a depression, the depression having a depth from a direction along a surface of the inner wall surface to a width direction of the groove, the inner bottom surface of the groove having protrusions with different heights and widths;

wherein some adjacent protrusions have an interval therebetween in a range of 10 μm or more and less than 100 μm, and other adjacent protrusions have an interval therebetween in a range of 1 μm or more and less than 10 μm.

2. The substrate according to claim **1**, wherein:

the inner wall surface has a plurality of the depressions; and

the depressions are spaced along a depth direction of the groove or along an inner periphery of the groove.

3. The substrate according to claim **1**, further comprising a semiconductor layer partly provided on the surface and extending along the inner wall surface.

4. The substrate according to claim **1**, further comprising a second surface provided on an opposite side of the surface and having a second groove, the second groove including a second inner wall surface.

5. The substrate according to claim **1**, wherein

the substrate is a silicon wafer, a silicon carbide wafer, a glass wafer, a quartz wafer, a sapphire wafer, or a compound semiconductor wafer.

6. The substrate according to claim **1**, wherein

the substrate has a circular shape when viewed from a direction perpendicular to the surface.

7. The substrate according to claim **1**, wherein

the inner wall surface is perpendicular to an inner side surface of the depression.

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